

ISOFACE™ Digital Isolator 4DIRx4xxH family

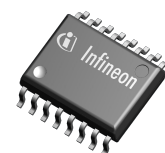
Robust Digital Isolators with precise timing and low power consumption

Description

The ISOFACE™ 4DIRx4xxH quad-channel digital isolator family supports data rates up to 40 Mbps and ensures robust data communication over a wide ambient operating temperature range (-40°C to +125°C) and across production spread. Infineon's robust Coreless Transformer (CT) technology provides high immunity against system noise (CMTI of min. 100 kV/μs) and withstands up to 5700 V_{rms} isolation voltage (V_{ISO}). Four data channels in a PG-DSO-16 wide-body 300 mil package allow simplified and high power density designs and improve system efficiency with low power consumption. Product variants with different channel configurations and fail-safe default output states are available.

Features

- Data rates up to 40 Mbps
- Wide operating supply voltage 2.7 V - 6.5 V
- Low current consumption (max. 1.6 mA/ch @ 1 Mbps, 3.3 V, 15 pF)
- High CMTI of min. 100 kV/μs
- Propagation delay typ 26 ns with 3 ns channel-to-channel mismatch
- Max 3 ns pulse width distortion @ 3.3 V
- Variable CMOS input thresholds with default output high or low options
- RoHS compliant PG-DSO-16 wide-body 300 mil package



Isolation and safety certificates

- UL 1577 (Ed. 5) with V_{ISO} = 5700 V_{rms} (certification n. E311313)
- VDE 0884-17 ¹⁾ and IEC 60747-17 with V_{IOTM} = 8000 V_{pk}, V_{IORM} = 1131 V_{pk}, V_{IOSM} = 10000 V_{pk} ²⁾
- EN and CQC certification for IEC 62368-1, IEC 60601-1, IEC 61010-1, GB 4943.1 system standards ²⁾

Product validation

Fully qualified according to JEDEC for industrial applications.

Potential applications

- Server, telecom and Industrial Switch-Mode Power Supplies (SMPS)
- Industrial automation systems
- Motor drives
- Medical equipments
- Isolated Serial Peripheral Interface (SPI)

¹ IEC 60747-17 and its German equivalent VDE 0884-17

² Certification planned

ISOFACE™ 4DIRx4xxH product portfolio

Part number	Channel configuration	Default output state	Output enable	Isolation rating	Package
4DIR0400H	4 forward 0 reverse (4+0)	Low	Active-high	$V_{ISO} = 5700 V_{rms}$ (UL1577 Ed. 5)	PG-DSO-16 wide-body 300 mil 10.3 x 10.3 mm
4DIR0401H		High			
4DIR1400H	3 forward 1 reverse (3+1)	Low			
4DIR1401H		High			
4DIR2400H	2 forward 2 reverse (2+2)	Low			
4DIR2401H		High			
4DIR1420H	3 forward 1 reverse (3+1)	Low	Active-low ¹⁾		
4DIR1421H		High			

1) Ideal for shared SPI bus

Application examples

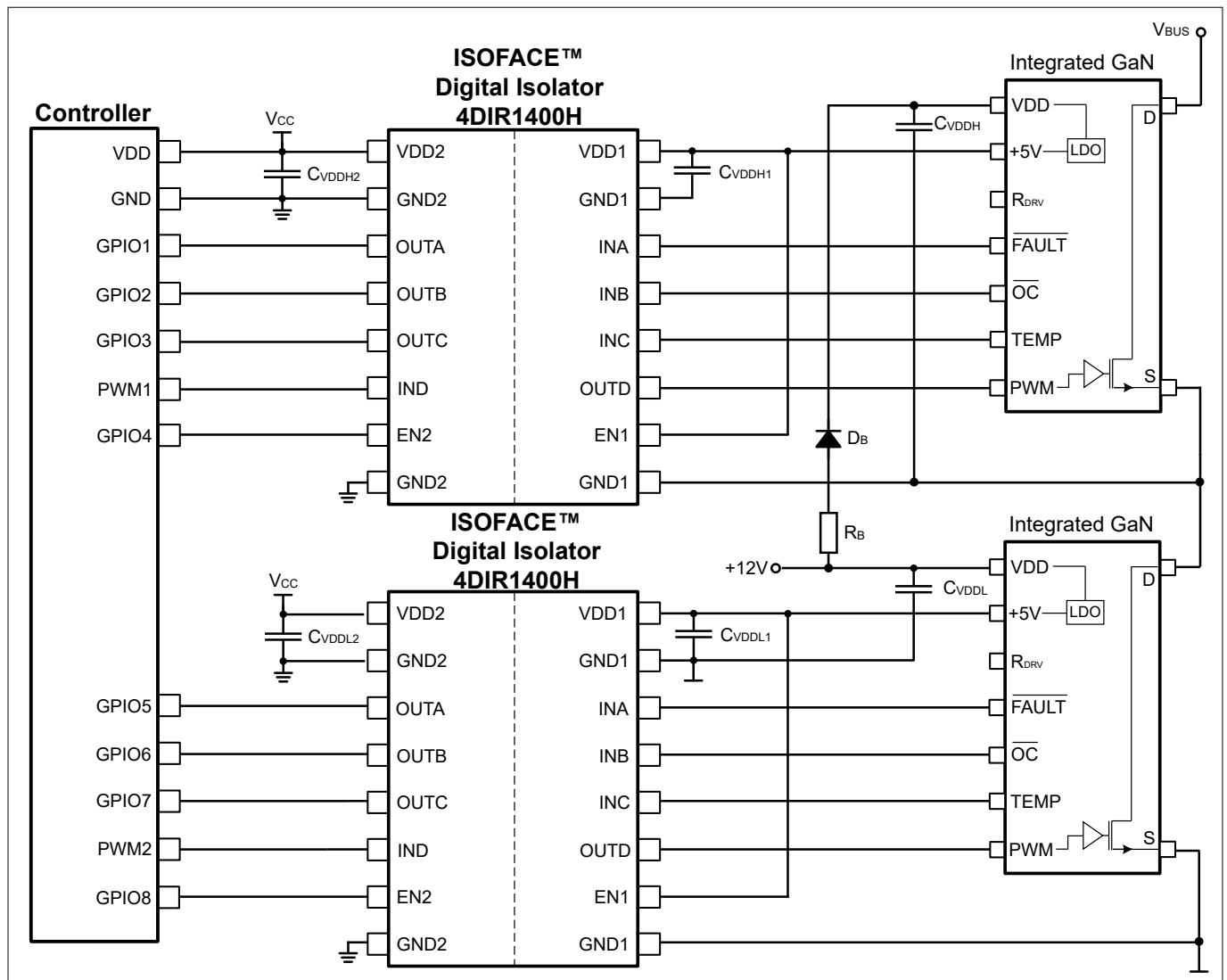


Figure 1 Typical application driving half-bridge using GaN integrated power stage (IPS)

Application examples

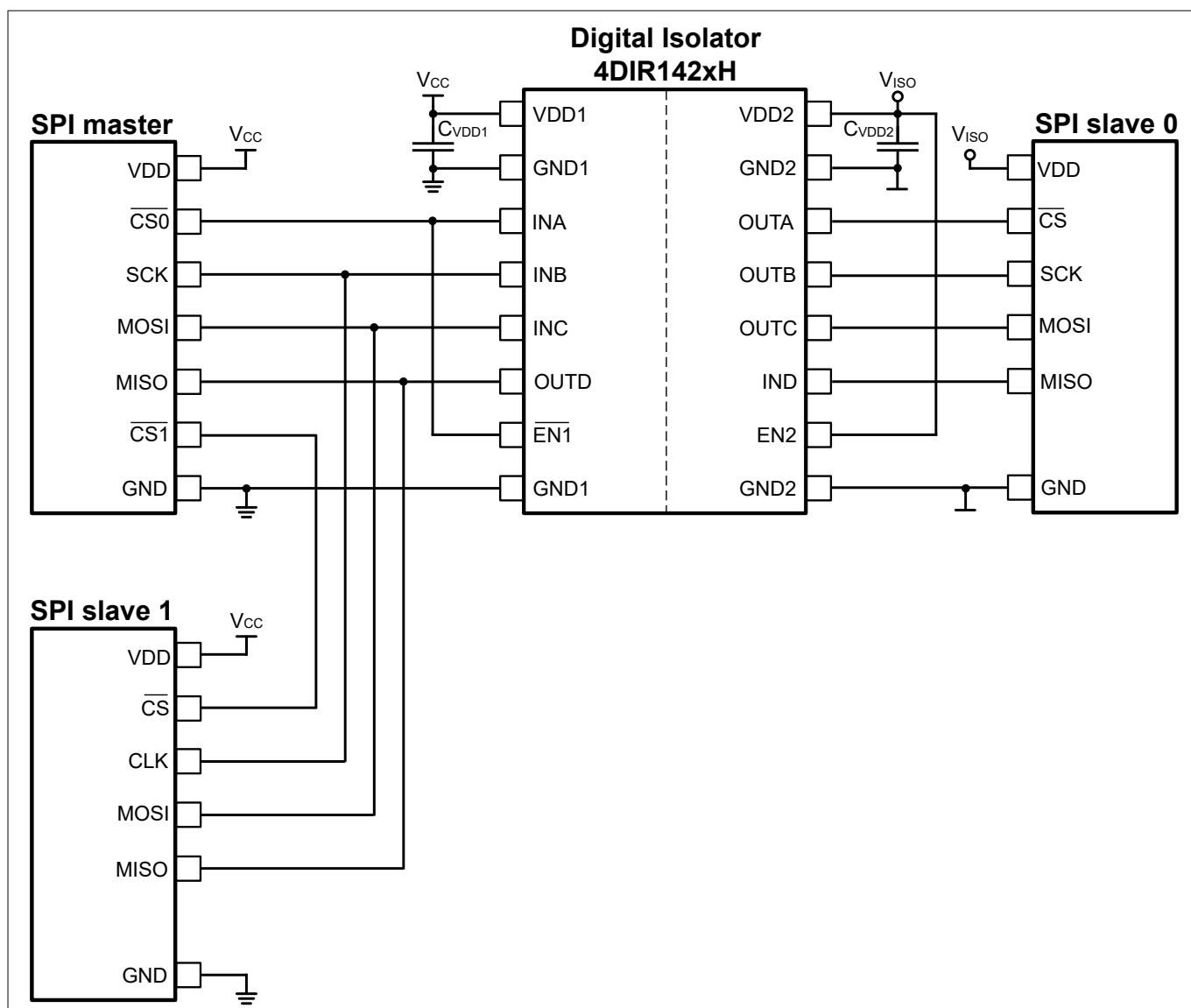


Figure 2 Typical application Isolated SPI bus

Table of contents

	Description	1
	Features	1
	Isolation and safety certificates	1
	Product validation	1
	Potential applications	1
	ISOFACE™ 4DIRx4xxH product portfolio	2
	Application examples	3
	Table of contents	5
1	Functional block diagram	7
2	Pin configuration	8
3	Functional description	12
3.1	Truth tables	12
3.2	Timing diagrams	13
3.3	Data transmission input-to-output	15
3.4	Input/output voltage levels description	15
3.5	Supply characteristics	16
4	Thermal and electrical characteristics	20
4.1	Absolute maximum ratings	20
4.2	Additional ESD ratings	20
4.3	Operating range	21
4.4	Common Mode Transient Immunity (CMTI)	21
4.5	Thermal characteristics	22
4.6	Power supply - UVLO	23
4.7	Electrical characteristics	24
4.7.1	Electrical characteristics - 6.5 V supply	24
4.7.1.1	Logic inputs	24
4.7.1.2	Logic outputs	24
4.7.1.3	Power supply - 4DIR040xH (4+0)	25
4.7.1.4	Power supply - 4DIR140xH (3+1)	26
4.7.1.5	Power supply - 4DIR240xH (2+2)	27
4.7.1.6	Power supply - 4DIR142xH (3+1 EN1 neg.)	28
4.7.1.7	Dynamic characteristics	29
4.7.2	Electrical characteristics - 5 V supply	31
4.7.2.1	Logic inputs	31
4.7.2.2	Logic outputs	31
4.7.2.3	Power supply - 4DIR040xH (4+0)	32

Table of contents

4.7.2.4	Power supply - 4DIR140xH (3+1)	33
4.7.2.5	Power supply - 4DIR240xH (2+2)	34
4.7.2.6	Power supply - 4DIR142xH (3+1 EN1 neg.)	35
4.7.2.7	Dynamic characteristics	36
4.7.3	Electrical characteristics - 3.3 V supply	38
4.7.3.1	Logic inputs	38
4.7.3.2	Logic outputs	38
4.7.3.3	Power supply - 4DIR040xH (4+0)	39
4.7.3.4	Power supply - 4DIR140xH (3+1)	40
4.7.3.5	Power supply - 4DIR240xH (2+2)	41
4.7.3.6	Power supply - 4DIR142xH (3+1 EN1 neg.)	42
4.7.3.7	Dynamic characteristics	43
4.7.4	Electrical characteristics - 2.7 V supply	45
4.7.4.1	Logic inputs	45
4.7.4.2	Logic outputs	45
4.7.4.3	Power supply - 4DIR040xH (4+0)	46
4.7.4.4	Power supply - 4DIR140xH (3+1)	47
4.7.4.5	Power supply - 4DIR240xH (2+2)	48
4.7.4.6	Power supply - 4DIR142xH (3+1 EN1 neg.)	49
4.7.4.7	Dynamic characteristics	50
4.8	Insulation and safety-related specifications	52
4.8.1	Insulation characteristics	52
4.8.2	Safety-limiting values	54
4.8.2.1	Thermal derating curve	54
5	Package dimensions	55
6	Ordering guide	58
7	Revision history	59
	Disclaimer	60

1 Functional block diagram

1 Functional block diagram

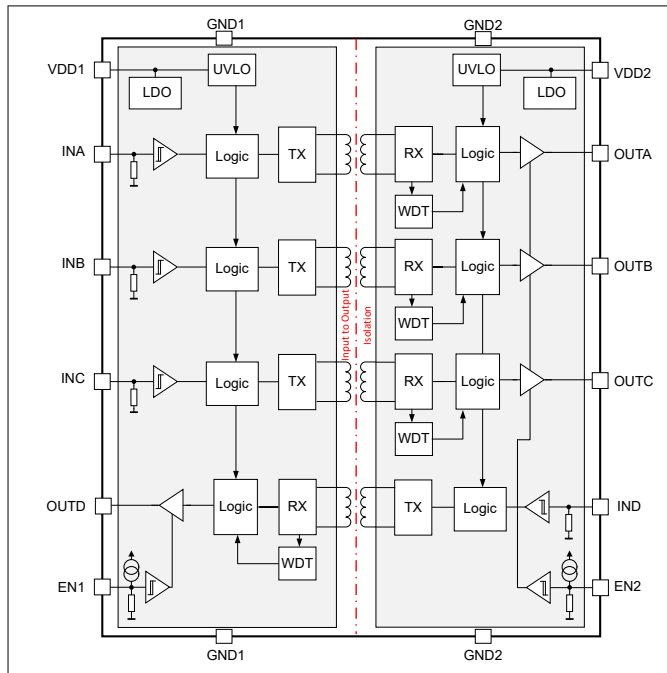


Figure 3 **3+1 digital isolator (4DIR140xH)**

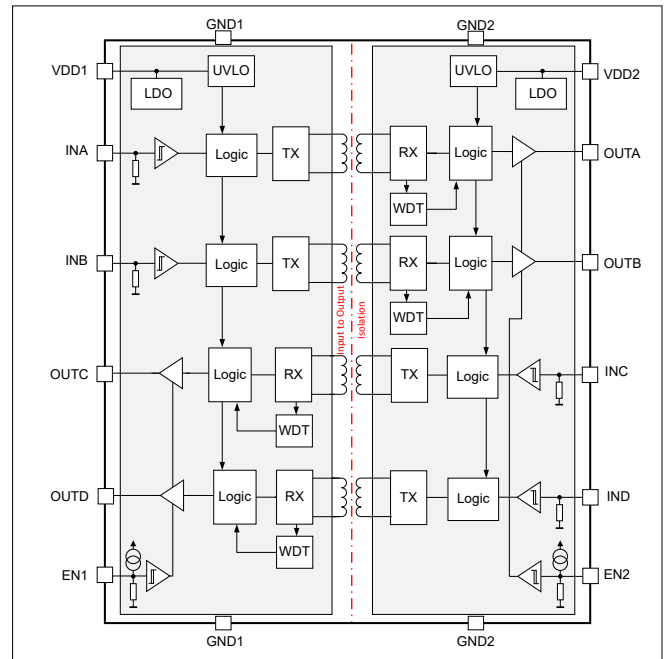


Figure 4 **2+2 digital isolator (4DIR240xH)**

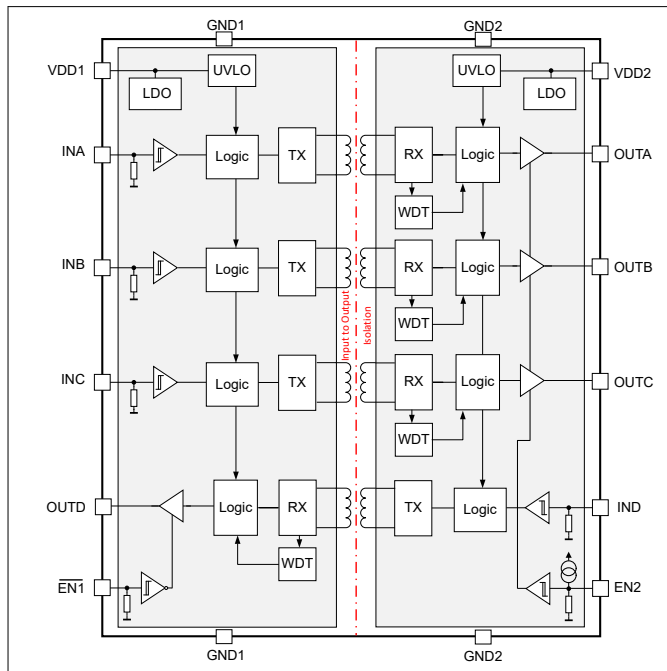


Figure 5 **3+1 EN1 neg. digital isolator (4DIR142xH)**

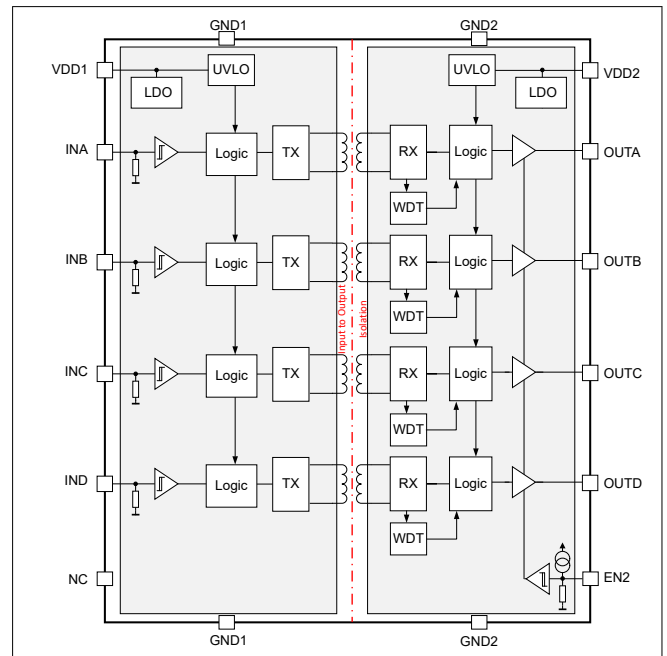


Figure 6 **4+0 digital isolator (4DIR040xH)**

Output enable for the side 1 ($\overline{EN1}$) of the 4DIR142xH is active-low, making it ideal for isolating a port on a shared SPI bus since the CS signal can directly enable the MISO signal on the isolator.

2 Pin configuration

2 Pin configuration

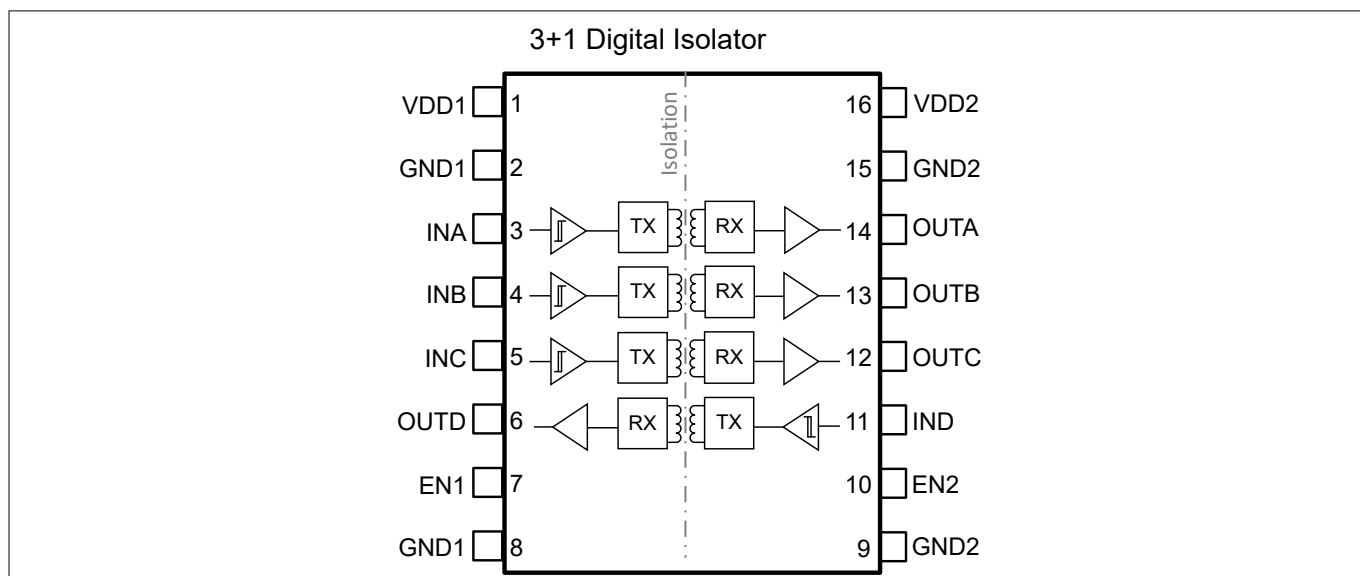


Figure 7 Pin-out for 4DIR140xH

Table 1 Pin definitions and functions for 4DIR140xH

Name	Pin	Type	Function
VDD1	1	I	Positive supply voltage 1
GND1	2	-	Ground 1
INA	3	I	Channel A input
INB	4	I	Channel B input
INC	5	I	Channel C input
OUTD	6	O	Channel D output
EN1	7	I	Enable 1 (internally pulled-up). Output pins on side 1 are enabled when EN1 is high or open and in high-impedance state when EN1 is low. Do not leave open. Connect to VDD1 to enable outputs or to GND1 to put outputs in high-impedance
GND1	8	-	Ground 1
GND2	9	-	Ground 2
EN2	10	I	Enable 2 (internally pulled-up). Output pins on side 2 are enabled when EN2 is high or open and in high-impedance state when EN2 is low. Do not leave open. Connect to VDD2 to enable outputs or to GND2 to put outputs in high-impedance
IND	11	I	Channel D input
OUTC	12	O	Channel C output
OUTB	13	O	Channel B output
OUTA	14	O	Channel A output
GND2	15	-	Ground 2
VDD2	16	I	Positive supply voltage 2

2 Pin configuration

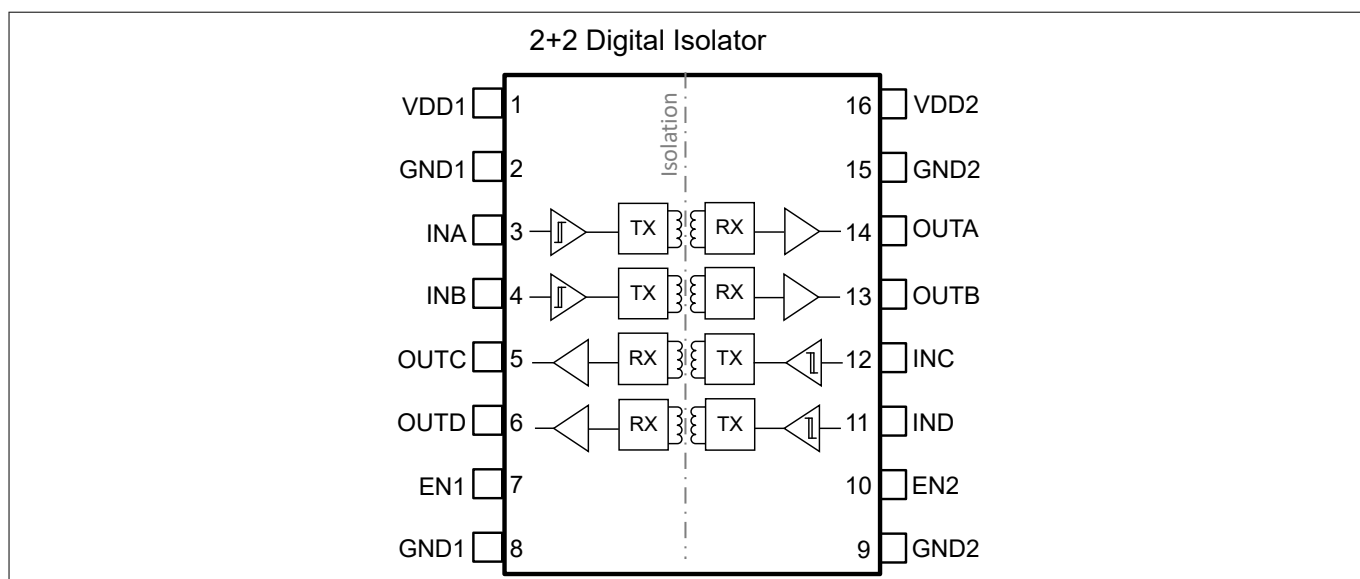


Figure 8 Pin-out for 4DIR240xH

Table 2 Pin definitions and functions for 4DIR240xH

Name	Pin	Type	Function
VDD1	1	I	Positive supply voltage 1
GND1	2	-	Ground 1
INA	3	I	Channel A input
INB	4	I	Channel B input
OUTC	5	O	Channel C output
OUTD	6	O	Channel D output
EN1	7	I	Enable 1 (internally pulled-up). Output pins on side 1 are enabled when EN1 is high or open and in high-impedance state when EN1 is low. Do not leave open. Connect to VDD1 to enable outputs or to GND1 to put outputs in high-impedance
GND1	8	-	Ground 1
GND2	9	-	Ground 2
EN2	10	I	Enable 2 (internally pulled-up). Output pins on side 2 are enabled when EN2 is high or open and in high-impedance state when EN2 is low. Do not leave open. Connect to VDD2 to enable outputs or to GND2 to put outputs in high-impedance
IND	11	I	Channel D input
INC	12	I	Channel C input
OUTB	13	O	Channel B output
OUTA	14	O	Channel A output
GND2	15	-	Ground 2
VDD2	16	I	Positive supply voltage 2

2 Pin configuration

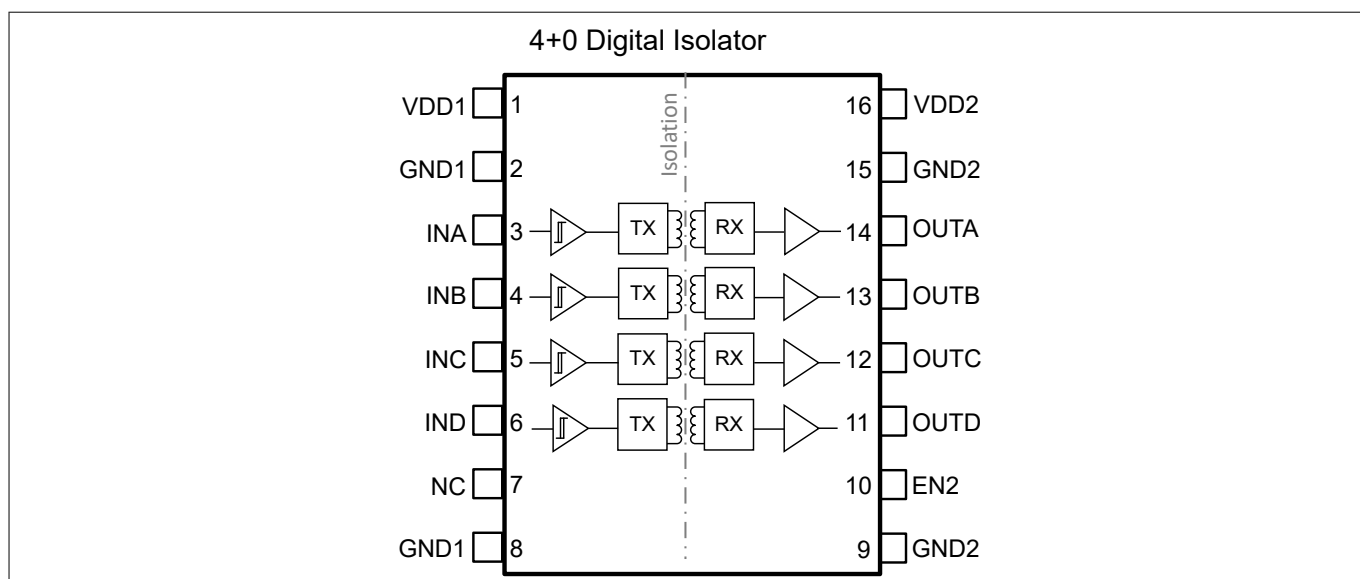


Figure 9 Pin-out for 4DIR040xH

Table 3 Pin definitions and functions for 4DIR040xH

Name	Pin	Type	Function
VDD1	1	I	Positive supply voltage 1
GND1	2	-	Ground 1
INA	3	I	Channel A input
INB	4	I	Channel B input
INC	5	I	Channel C input
IND	6	I	Channel D input
NC	7	-	No connect. Leave this pin floating
GND1	8	-	Ground 1
GND2	9	-	Ground 2
EN2	10	I	Enable 2 (internally pulled-up). Output pins on side 2 are enabled when EN2 is high or open and in high-impedance state when EN2 is low. Do not leave open. Connect to VDD2 to enable outputs or to GND2 to put outputs in high-impedance
OUTD	11	O	Channel D output
OUTC	12	O	Channel C output
OUTB	13	O	Channel B output
OUTA	14	O	Channel A output
GND2	15	-	Ground 2
VDD2	16	I	Positive supply voltage 2

2 Pin configuration

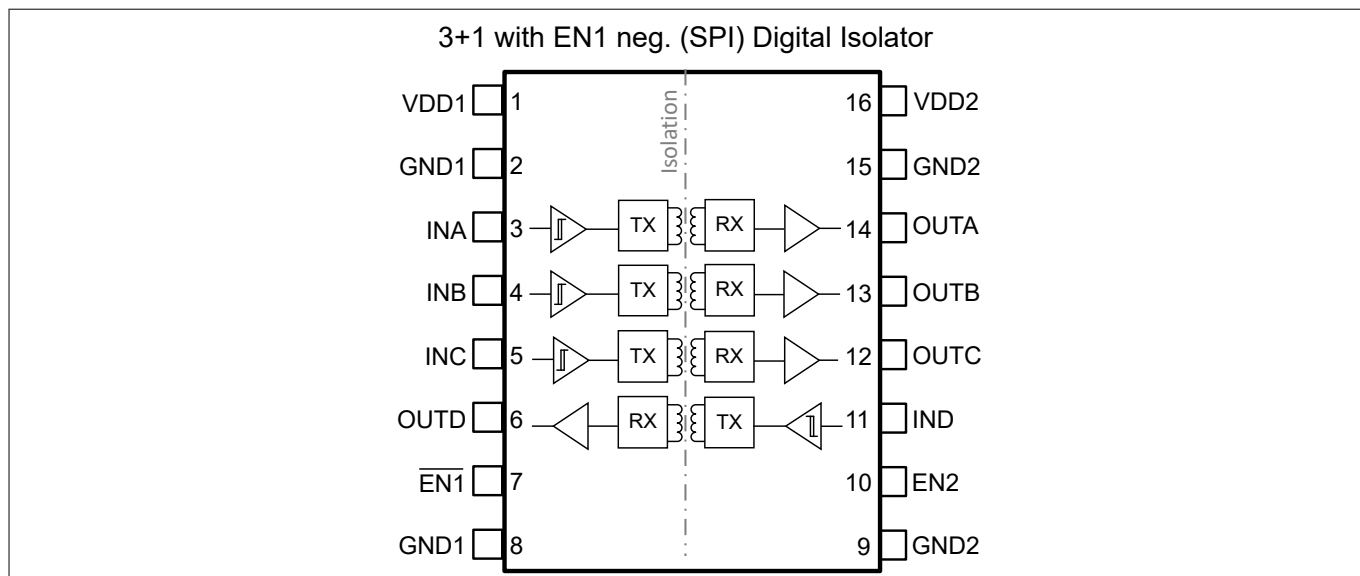


Figure 10 Pin-out for 4DIR142xH

Table 4 Pin definitions and functions for 4DIR142xH

Name	Pin	Type	Function
VDD1	1	I	Positive supply voltage 1
GND1	2	-	Ground 1
INA	3	I	Channel A input
INB	4	I	Channel B input
INC	5	I	Channel C input
OUTD	6	O	Channel D output
EN1	7	I	Negated enable 1 (internally pulled-down). Output pins on side 1 are enabled when EN1 is low or open and in high-impedance state when EN1 is high. Do not leave open. Connect to GND1 to enable outputs or to VDD1 to put outputs in high-impedance
GND1	8	-	Ground 1
GND2	9	-	Ground 2
EN2	10	I	Enable 2 (internally pulled-up). Output pins on side 2 are enabled when EN2 is high or open and in high-impedance state when EN2 is low. Do not leave open. Connect to VDD2 to enable outputs or to GND2 to put outputs in high-impedance
IND	11	I	Channel D input
OUTC	12	O	Channel C output
OUTB	13	O	Channel B output
OUTA	14	O	Channel A output
GND2	15	-	Ground 2
VDD2	16	I	Positive supply voltage 2

3 Functional description

3 Functional description

This chapter provides a summary of the integrated functions and features, and describes the relationships between them. The parameters and equations are based on typical values at $T_A = 25\text{ °C}$.

3.1 Truth tables

Table 5 Truth table for 4-channel Digital Isolator

V_{DDI}	V_{DDO}	$V_{ENX}^{1)}$	V_{INX}	V_{OUTX}
Powered	Powered	H or NC ²⁾	H	H
			L	L
		L	X ³⁾	Z ⁴⁾
Unpowered	Powered	H or NC	X	Default ⁵⁾
		L	X	Z
X	Unpowered	X	X	Z

1) EN1 controls the output on side 1 and EN2 controls the outputs on side 2

2) Not connected

3) X means "irrelevant"

4) Z means "high-impedance"

5) Refer to product variants

Table 6 Truth table for 4-channel Digital Isolator (3+1 EN1 neg. digital isolator)

V_{DDI}	V_{DDO}	$V_{EN1}^{1)}$	$V_{EN2}^{2)}$	V_{INX}	V_{OUTX}
Powered	Powered	L or NC	H or NC	H	H
				L	L
		H	L	X	Z
Unpowered	Powered	L or NC	H or NC	X	Default
		H	L	X	Z
X	Unpowered	X	X	X	Z

1) Controls the outputs on side 1

2) Controls the outputs on side 2

3 Functional description

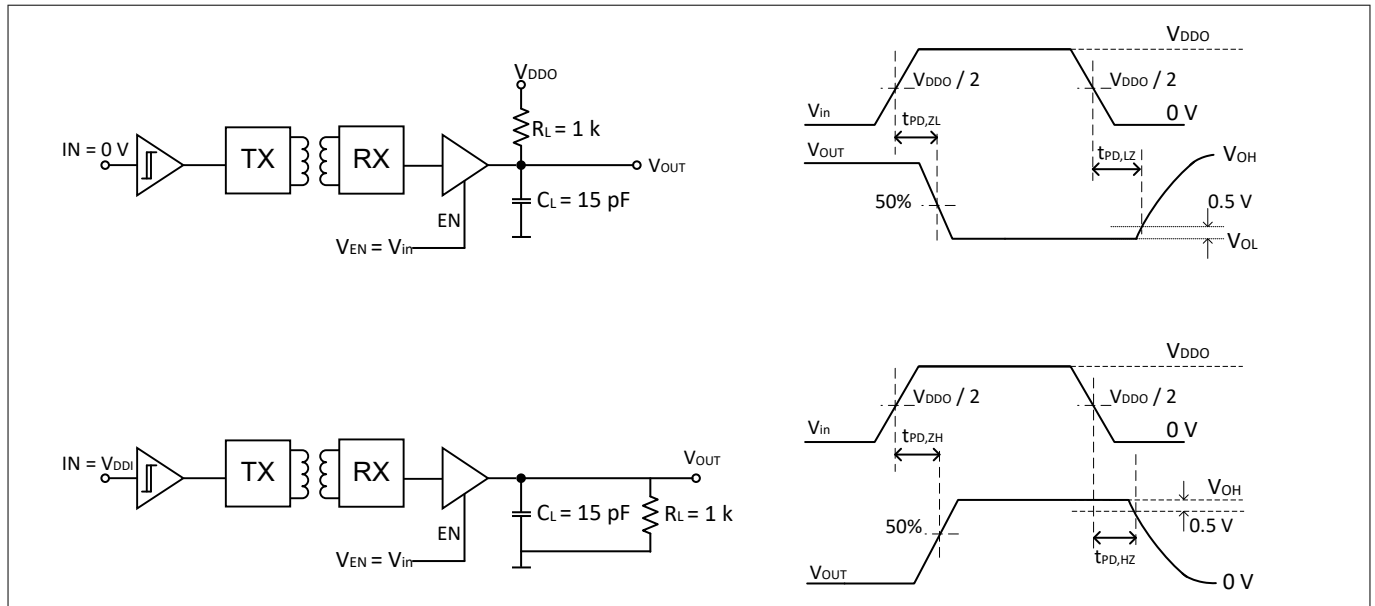


Figure 15 Output enable/disable propagation delays

Figure 16 illustrates the time to default output state when the input loses supply.

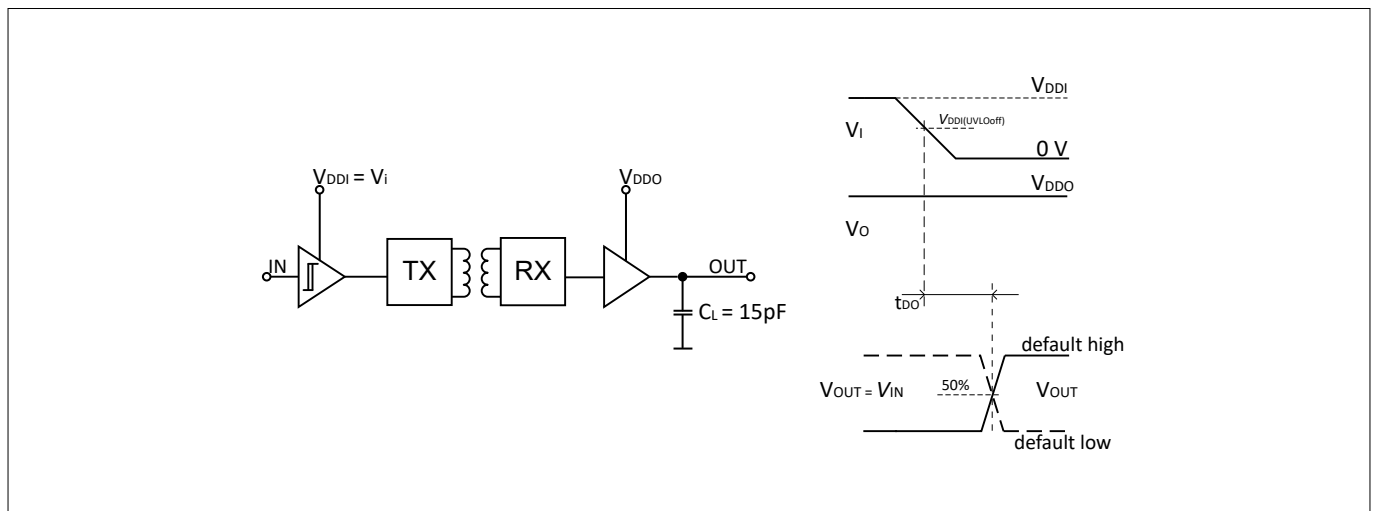


Figure 16 Default output delay time

Figure 17 illustrates the output behavior when input and output side supplies have different power-up timings where the power-up time is $t_{PU} = \max\{t_{PU1}, t_{PU2}\}$.

3 Functional description

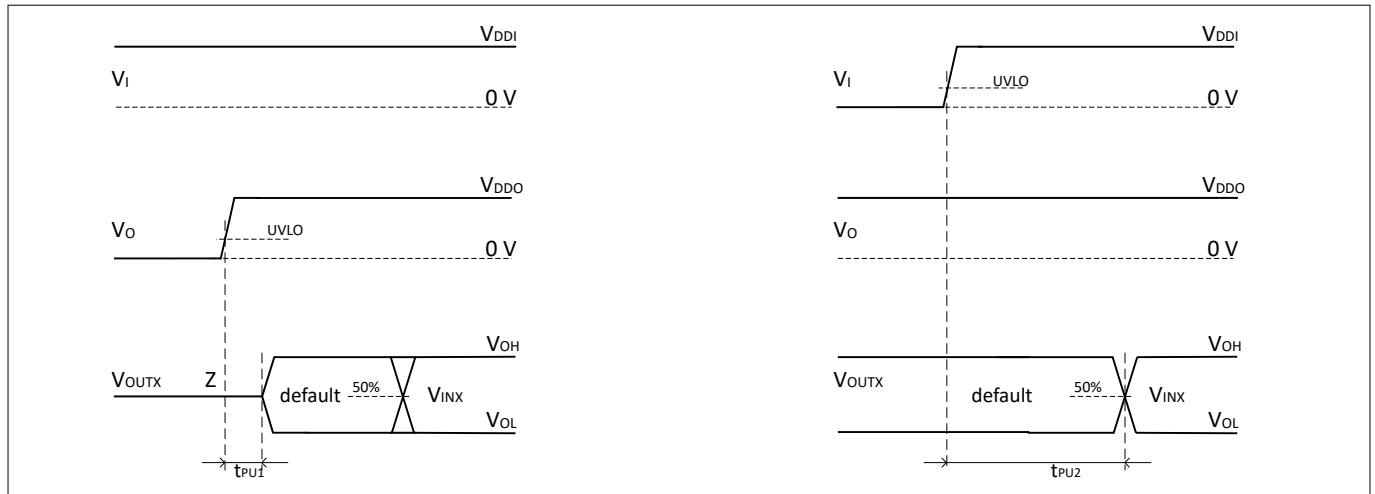


Figure 17 Power-up delay time

3.3 Data transmission input-to-output

Communication based on Coreless Transformer (CT) is used for signal transfer between input and output channels. If a constant DC level within the operating range is applied at the input, a proven high resolution pulse repetition scheme ensure functionality, enabling the output to follow the constant DC input. It also enables recovery from communication fails and safe system shutdown. In case of a power loss at the input channel, the pulse repetition scheme will be disabled and a watch-dog timer at the output triggers approximately after t_{DO} time period and drives the channel output to the default state. In case of multiple channels on the output side, the first watch-dog timer detecting the power loss at the input will drive all output channels on that side to default value. Once the power supply on the input channels is above the threshold value ($V_{DDX(UVLOon)}$), the communication is restored and the output will follow the input as shown in [Figure 17](#).

3.4 Input/output voltage levels description

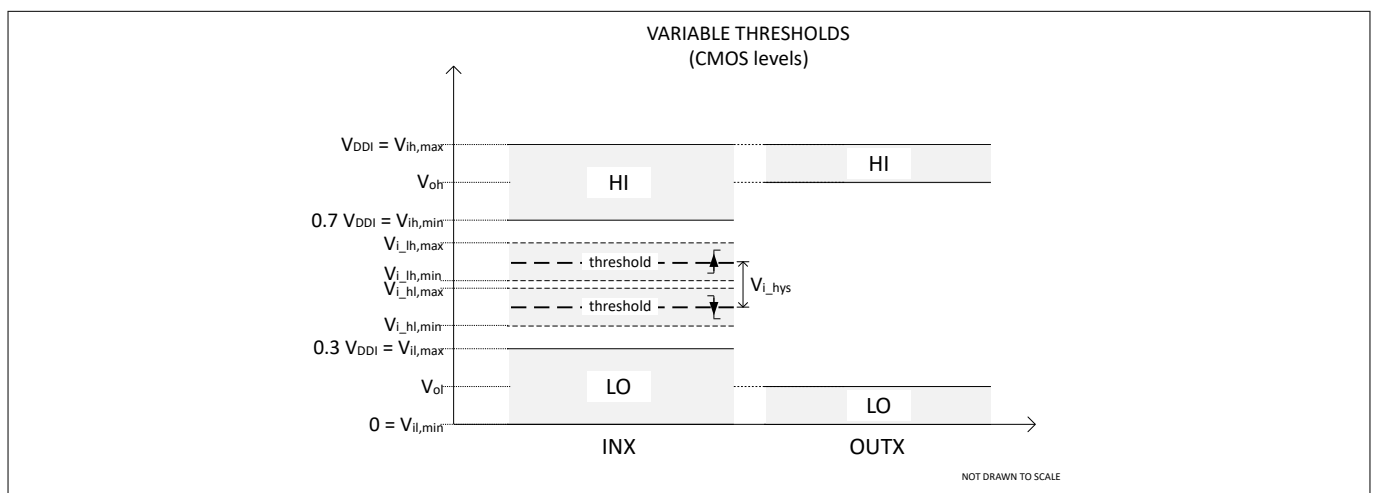


Figure 18 CMOS variable thresholds description

3 Functional description

3.5 Supply characteristics

Maximum values are given at $T_A = 125^\circ\text{C}$, $C_{\text{LOAD}} = 15\text{ pF}$ and 50% duty cycle input square wave.

3+1 digital isolator (4DIR140xH)

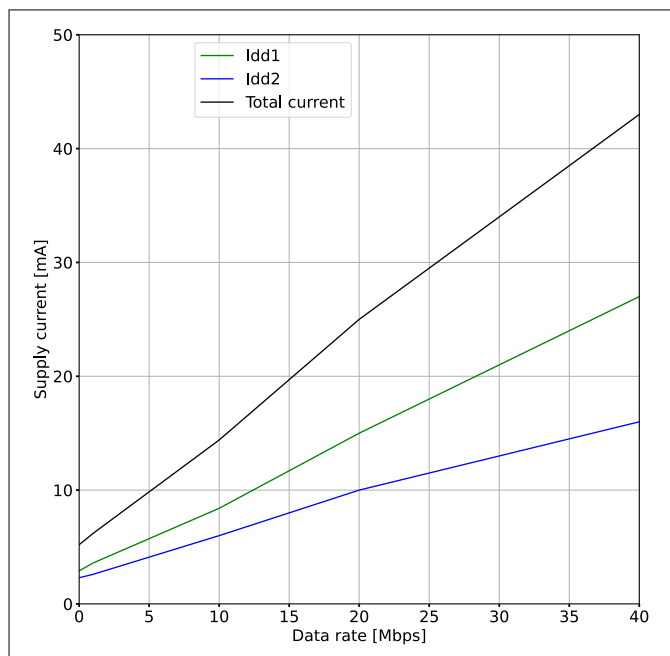


Figure 19 Supply current vs. data rate
($V_{\text{DD1}} = V_{\text{DD2}} = 6.5\text{ V}$)

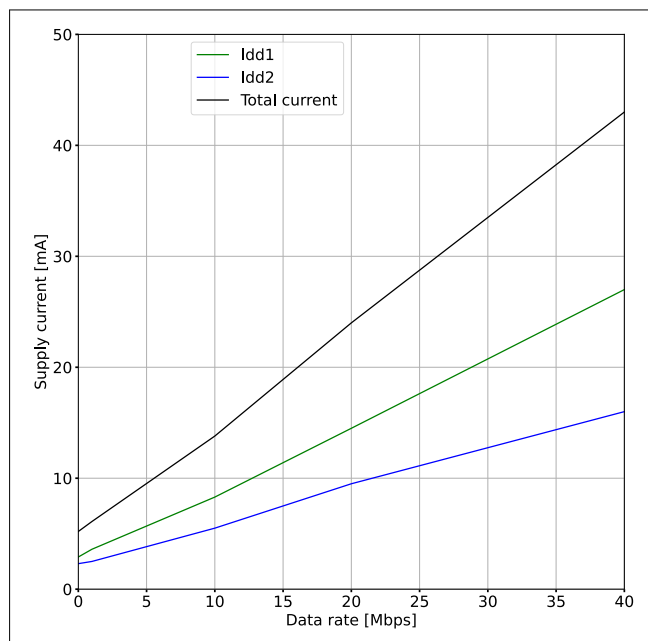


Figure 20 Supply current vs. data rate
($V_{\text{DD1}} = V_{\text{DD2}} = 5.0\text{ V}$)

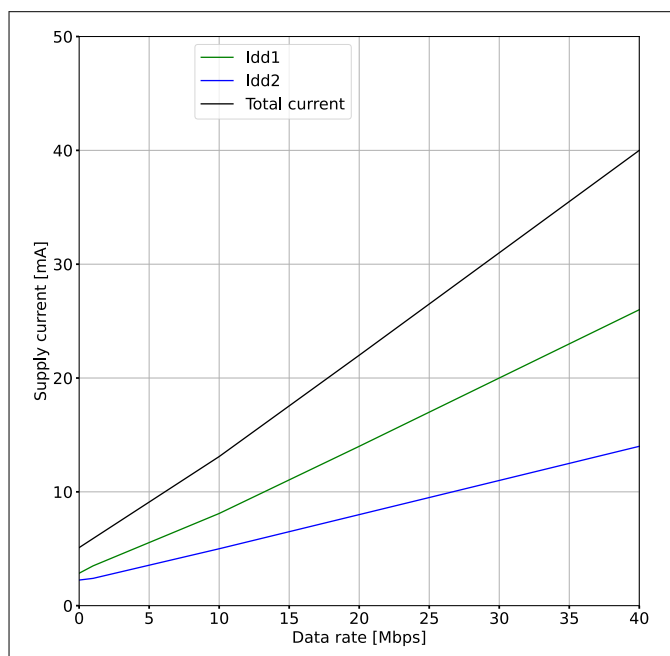


Figure 21 Supply current vs. data rate
($V_{\text{DD1}} = V_{\text{DD2}} = 3.3\text{ V}$)

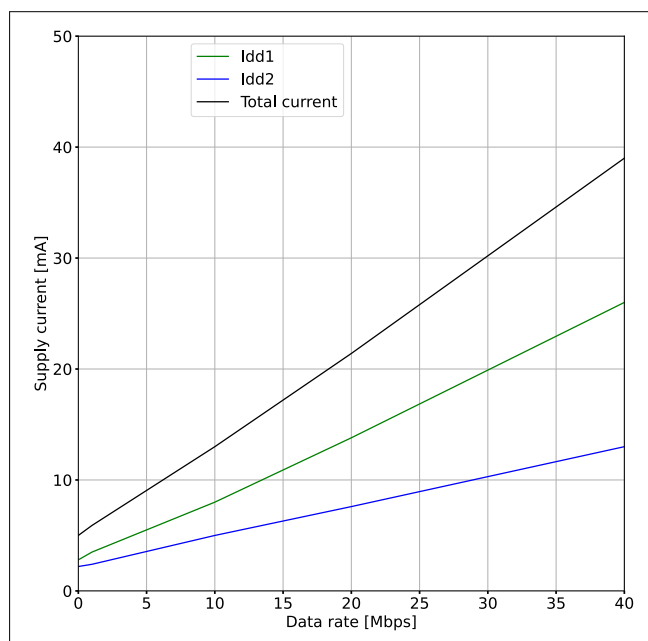


Figure 22 Supply current vs. data rate
($V_{\text{DD1}} = V_{\text{DD2}} = 2.7\text{ V}$)

3 Functional description

3+1 EN1 neg. digital isolator (4DIR142xH)

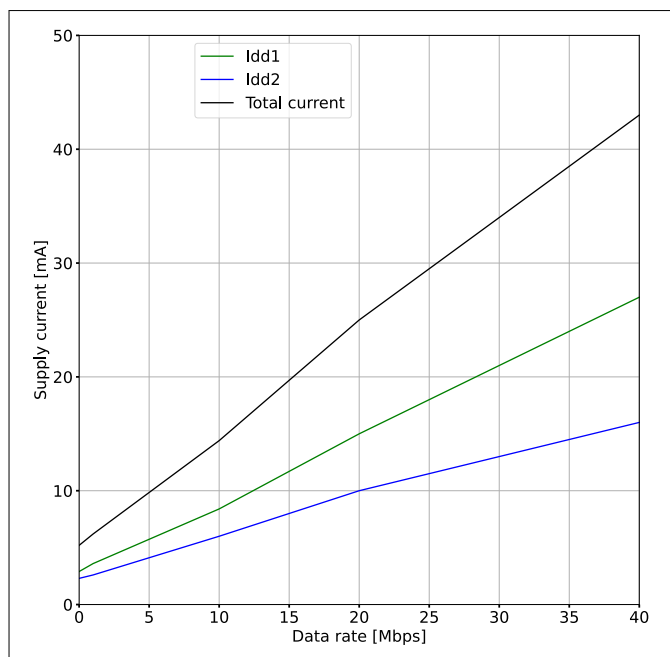


Figure 23 Supply current vs. data rate
($V_{DD1} = V_{DD2} = 6.5 \text{ V}$)

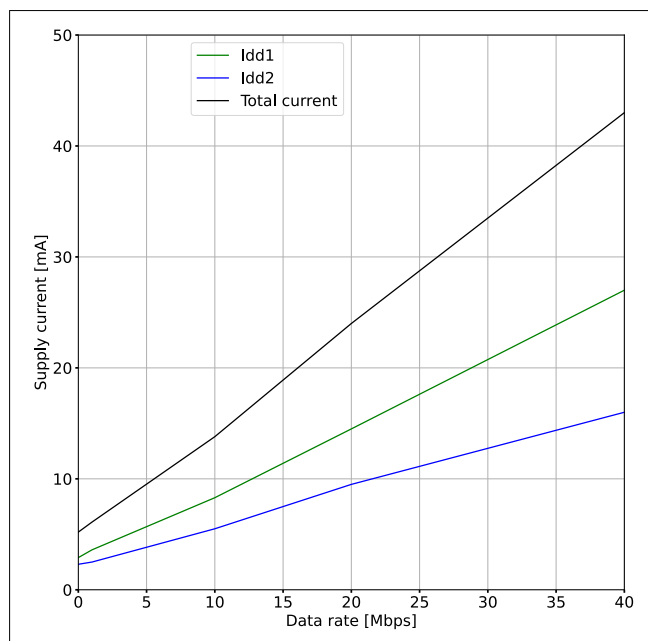


Figure 24 Supply current vs. data rate
($V_{DD1} = V_{DD2} = 5 \text{ V}$)

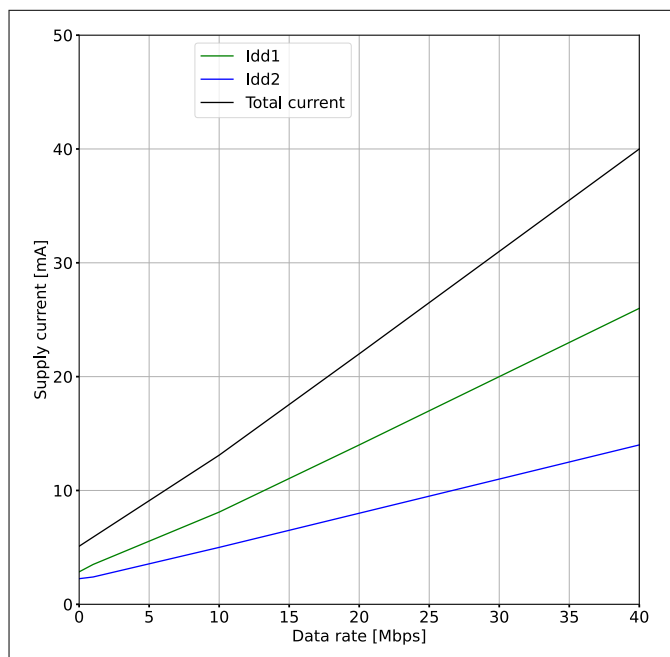


Figure 25 Supply current vs. data rate
($V_{DD1} = V_{DD2} = 3.3 \text{ V}$)

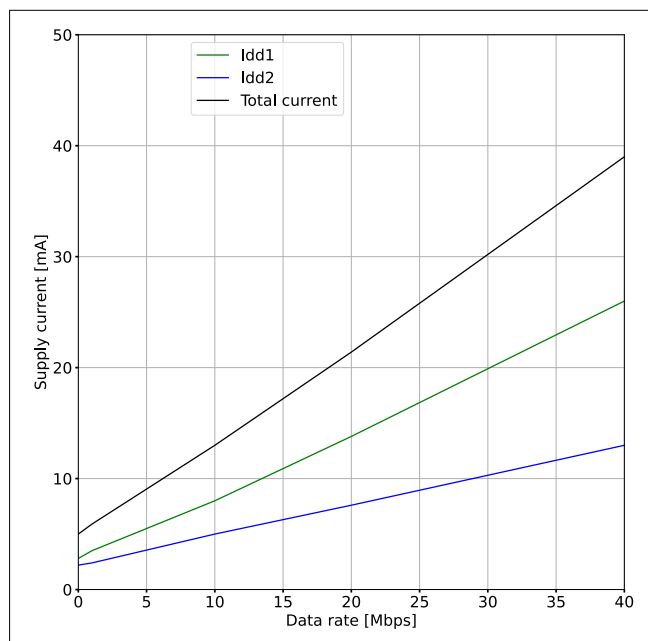


Figure 26 Supply current vs. data rate
($V_{DD1} = V_{DD2} = 2.7 \text{ V}$)

3 Functional description

2+2 digital isolator (4DIR240xH)

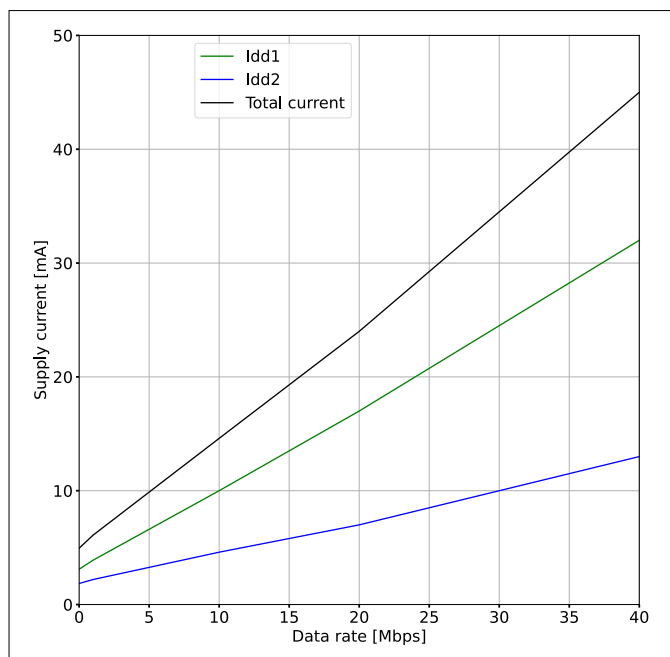


Figure 27 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 6.5 V)

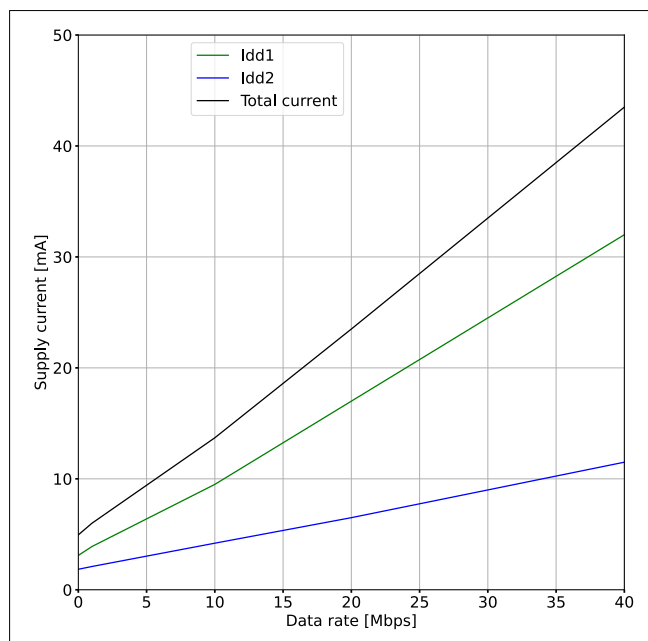


Figure 28 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 5 V)

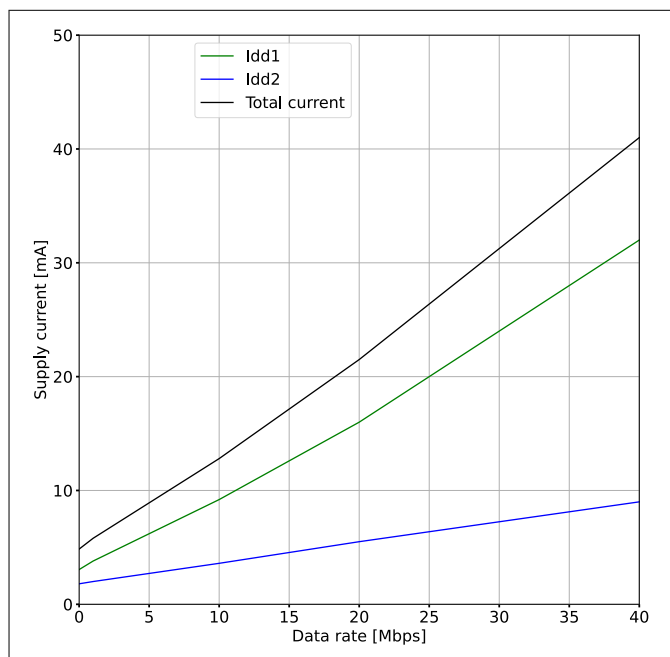


Figure 29 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 3.3 V)

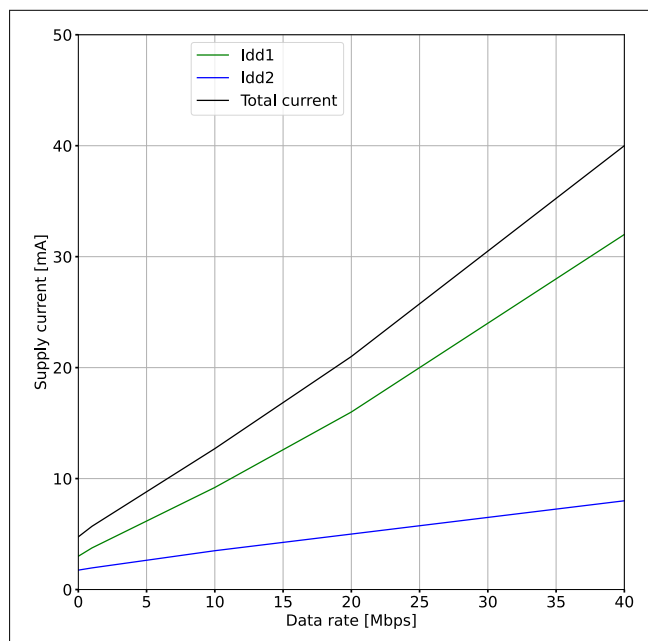


Figure 30 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 2.7 V)

3 Functional description

4+0 digital isolator (4DIR040xH)

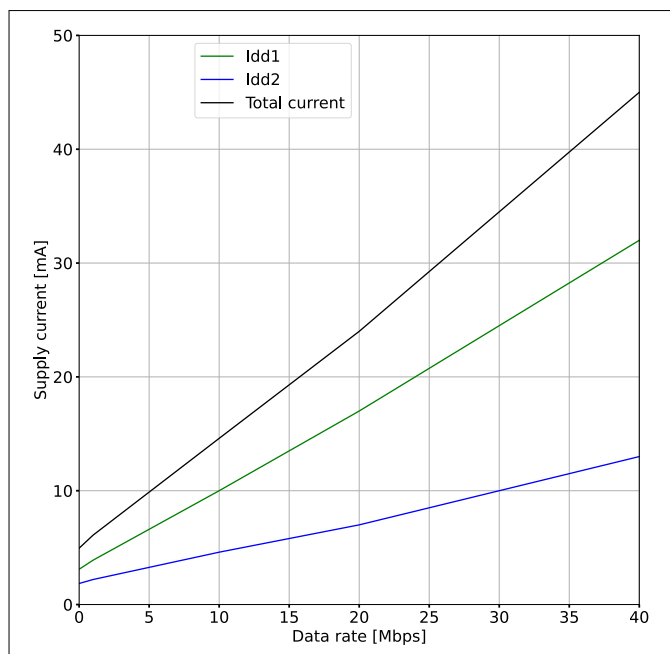


Figure 31 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 6.5 V)

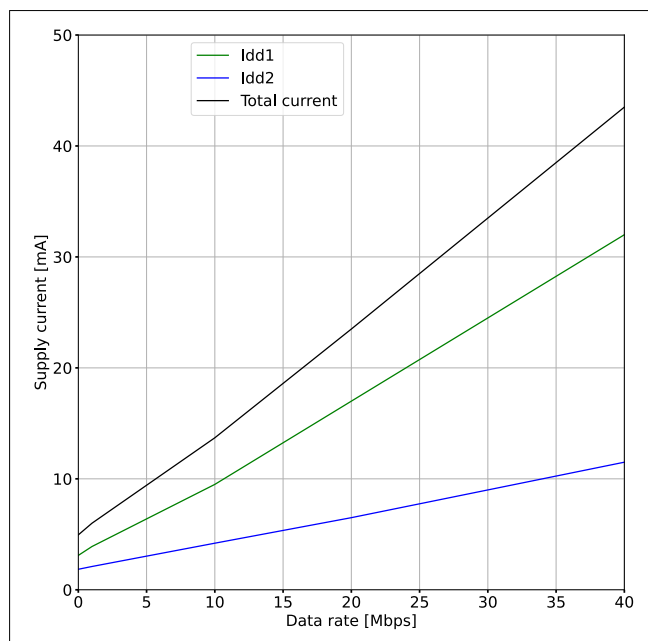


Figure 32 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 5 V)

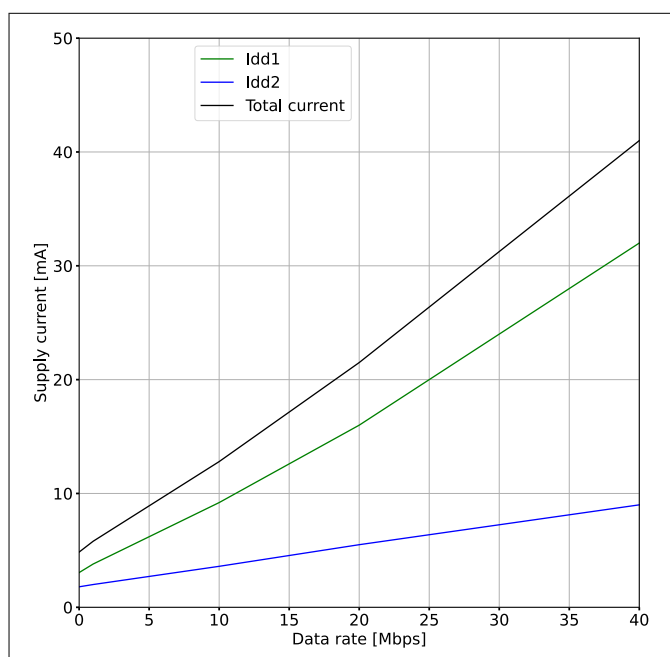


Figure 33 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 3.3 V)

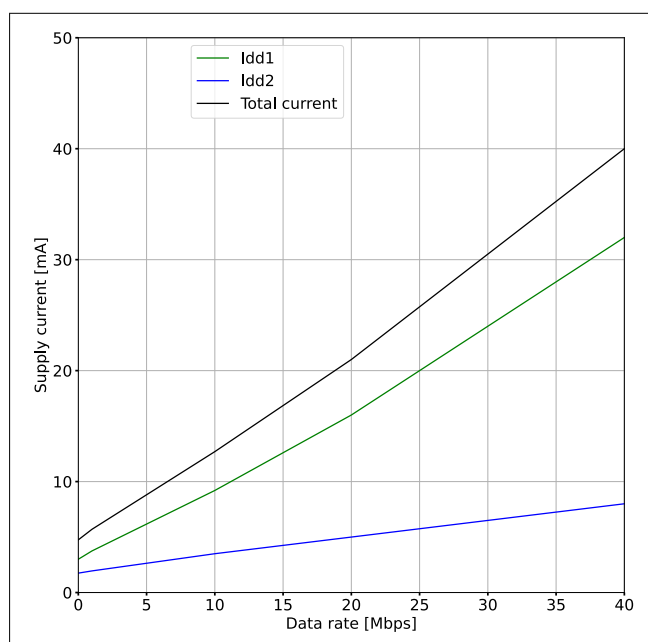


Figure 34 Supply current vs. data rate
(V_{DD1} = V_{DD2} = 2.7 V)

4 Thermal and electrical characteristics

4 Thermal and electrical characteristics

4.1 Absolute maximum ratings

Table 7 Absolute maximum ratings

Note: Stresses above the values listed below may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding these values may cause irreversible damage to the integrated circuit. These values are not tested during production test.

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply voltage	V_{DD1}, V_{DD2}	-0.5		7.5	V	
Voltage at pins INx	V_{INX}			$V_{DD1} + 0.5$	V	1)
Voltage at pins OUTx	V_{OUTX}			$V_{DDO} + 0.5$	V	1)
Average output current per pin	I_{OUT}	-10		+10	mA	
Junction temperature	T_J	-40		150	°C	
Storage temperature	T_{STG}	-65		150	°C	
Soldering temperature	T_{SOL}			260	°C	reflow soldering according to JEDEC-J-STD-020
Electrostatic discharge HBM	V_{ESD_HBM}	-2		2	kV	Human Body Model (HBM) according to JESD22-A114-B (discharging 100 pF capacitor through 1.5 kΩ resistor)
Electrostatic discharge CDM	V_{ESD_CDM}	-1.75		1.75	kV	Charged Device Model (CDM) according to JESD22-002
Latch-up capability	I_{LU}			150	mA	Latch-up immunity characterization according to JEDEC78E Class II, pin voltages according to abs. max. ratings

1) V_{DD1} and V_{DDO} refer to the supply voltages on the input and output sides of a given channel, respectively

4.2 Additional ESD ratings

Table 8 Additional ESD ratings

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Contact discharge per IEC 61000-4-2	$ V_{ESD_IEC} $		22		kV	Isolation barrier withstand test ^{1) 2)}

1) IEC ESD strike is applied across the barrier with all pins on each side tied together creating a two-terminal device.

2) Testing is carried out in air or oil to determine the intrinsic contact discharge capability of the device.

4 Thermal and electrical characteristics

4.3 Operating range

Table 9 Operating range

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Data rate	DR	0		40	Mbps	
Supply voltage	V_{DD1}, V_{DD2}	2.7		6.5	V	
High-level input voltage	V_{IH}	$0.7 V_{DD1}$		V_{DD1}	V	1)
Low-level input voltage	V_{IL}	0		$0.3 V_{DD1}$	V	1)
Ambient temperature	T_A	-40		125	°C	

1) V_{DD1} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4.4 Common Mode Transient Immunity (CMTI)

Table 10 Common Mode Transient Immunity (CMTI)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Static Common Mode Transient Immunity (CMTI)	$ CM_H $	100			kV/μs	$V_{CM} = 1200\text{ V}$; V_{INX} tied to V_{DD1} 1) 2) 3)
Static Common Mode Transient Immunity (CMTI)	$ CM_L $	100			kV/μs	$V_{CM} = 1200\text{ V}$; V_{INX} tied to GNDX 2) 3)

1) V_{DD1} - refers to the supply voltages on the input side of a given channel

2) Minimum slew rate of a common mode voltage at which the output signal is disturbed

3) Parameters not tested in production

4 Thermal and electrical characteristics

4.5 Thermal characteristics

Typical thermal characteristics at $T_A = 25^\circ\text{C}$

Table 11 Thermal characteristics for JEDEC and Reference PCB

Parameter	Symbol	JEDEC	Reference PCB	Unit	Note or condition
Thermal resistance junction-to-ambient	R_{thJA}	60 ¹⁾	59 ²⁾	K/W	JEDEC 2s2p (JED51-7), $P_{dis} = 378$ mW
Thermal resistance junction-to-case (top)	R_{thJC}	27	27	K/W	³⁾
Thermal resistance junction-to-board	R_{thJB}	20	30	K/W	⁴⁾
Characterization parameter junction-to-top	Ψ_{thJT}	3.4	3	K/W	⁵⁾
Characterization parameter junction-to-board	Ψ_{thJB}	20	20	K/W	⁵⁾

1) Obtained by simulating a JEDEC - standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a

2) Obtained by simulating a JEDEC-standard, high-K board, as specified in JESD51-7 and in reference PCB specifications below, in an environment described in JESD51-2a

3) Obtained by simulating a cold plate test on the package top. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88

4) Obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8

5) Estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining R_{th} , using a procedure described in JESD51-2a (sections 6 and 7)

Table 12 Reference PCB specifications

Parameter	Value	λ_{therm} [W/(m-K)]
Dimension [mm ³]	76.2 x 114.3 x 1.5 (JEDEC)	
Material	FR4	0.3
Metalization	JEDEC 2s2p (JESD 51-7)	388
Cooling area	Ground inner layer	
Thermal vias	Ø = 0.5mm; plating 25µm; 4 x 2 pcs. connected to ground inner layer	
Package attach [50 µm]	Solder	55
Ground inner layer [mm ³]	74.2 x 74.2 x 0.03 (JEDEC), planes are 8.2 mm spaced	

4 Thermal and electrical characteristics

Table 13 **Reference PCB layout**

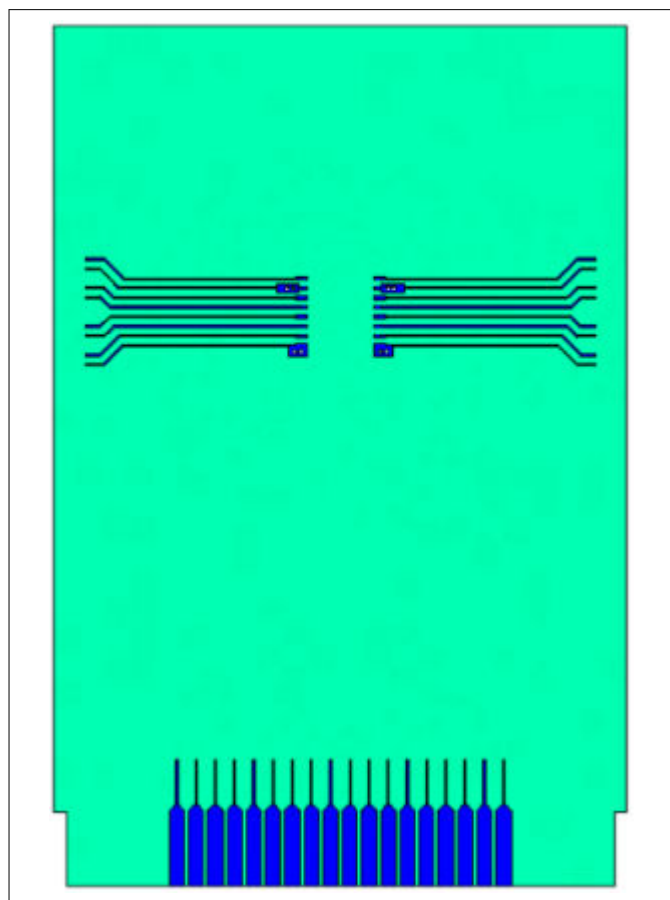


Figure 35 **Top footprint**

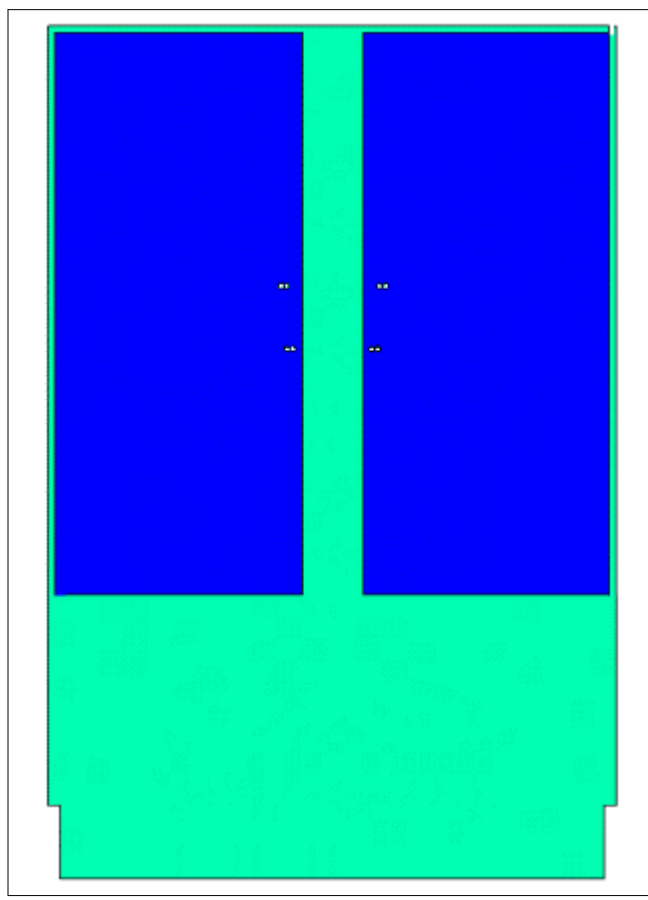


Figure 36 **Inner layers (connect to ground)**

4.6 Power supply - UVLO

Table 14 **Power supply - UVLO**

Typical values are given at $T_A = 25\text{ °C}$ over operating range unless otherwise specified.

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply UVLO turn-on threshold	$V_{DDX(UVLOon)}$	2.42	2.55	2.68	V	
Supply UVLO turn-off threshold	$V_{DDX(UVLOoff)}$	2.35	2.45	2.55	V	
Supply UVLO hysteresis	$V_{DDX(UVLOhys)}$	0.07	0.10		V	

4 Thermal and electrical characteristics

4.7 Electrical characteristics

The electrical characteristics involve the spread of values given within the specified operating conditions.

4.7.1 Electrical characteristics - 6.5 V supply

Typical values are given at $T_A = 25^\circ\text{C}$ with $V_{DD1} = V_{DD2} = 6.5\text{ V}$. Minimum/maximum specifications apply over the entire recommended operation range of $V_{DD1} = V_{DD2} = 6.5\text{ V}$, and $-40^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$, unless otherwise noted. Switching characteristics are tested with $C_{LOAD} = 15\text{ pF}$ and 50% duty-cycle input square wave, over operating range unless otherwise specified. Supply current values are specified considering that all channels are switching at the same data rate. Parameters are not tested in production unless otherwise specified.

4.7.1.1 Logic inputs

Table 15 Logic inputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level input current	I_{IH}			10	μA	$V_{INX} = V_{DD1}$ ^{1) 2)}
Low-level input current	I_{IL}	-10			μA	$V_{INX} = 0\text{ V}$ ²⁾
Input voltage threshold for transition LH	V_{I_LH}			$0.7 V_{DI}$	V	
Input voltage threshold for transition HL	V_{I_HL}	$0.3 V_{DI}$			V	
Input voltage threshold hysteresis	V_{I_HYS}	$0.1 V_{DI}$			V	
Input pull-down resistor	R_{IN}		825		$\text{k}\Omega$	$V_{INX} = V_{DD1}$ ¹⁾

1) V_{DD1} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

2) Parameter tested in production

4.7.1.2 Logic outputs

Table 16 Logic outputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level output voltage	V_{OH}	$V_{DDO} - 0.4$			V	$I_{OH} = 4\text{ mA}$ ¹⁾
Low-level output voltage	V_{OL}			0.4	V	$I_{OL} = -4\text{ mA}$

1) V_{DDO} - Output-side supply voltage. For output buffers on side 1 it is V_{DD1} and for output buffers on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.1.3 Power supply - 4DIR040xH (4+0)

Table 17 Power supply - 4DIR040xH (4+0)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			3.1	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			1.85	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			3.1	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			1.85	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.9	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			10	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			4.6	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			17	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			7	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			32	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			13	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.1.4 Power supply - 4DIR140xH (3+1)

Table 18 Power supply - 4DIR140xH (3+1)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.6	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.6	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.4	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			6	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			15	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			10	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			27	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			16	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.1.5 Power supply - 4DIR240xH (2+2)

Table 19 Power supply - 4DIR240xH (2+2)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.7	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.7	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.7	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.7	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			3.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			7.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			7.0	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			13	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			12	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			23	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			21	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.1.6 Power supply - 4DIR142xH (3+1 EN1 neg.)

Table 20 Power supply - 4DIR142xH (3+1 EN1 neg.)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.6	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.4	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			6	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			15	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			10	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			27	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			16	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.1.7 Dynamic characteristics

Table 21 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
INx to OUTx turn-on propagation delay	$t_{PD\text{on}}$	21	26	33	ns	From 50% level of rising input to 50% level of corresponding rising output ¹⁾
INx to OUTx turn-off propagation delay	$t_{PD\text{off}}$	21	26	33	ns	From 50% level of rising input to 50% level of corresponding rising output ¹⁾
Part-to-part propagation delays mismatch	$\Delta t_{PD,p-p}$			6	ns	^{1) 2)}
Co-directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3.5	ns	Within same sample, over operating temperature range, same direction channels, switching in the same direction ¹⁾
Opposing directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3.5	ns	Within same sample, over operating temperature range, opposing directional channels, switching with the same signal level ¹⁾
Pulse width distortion	PWD			3	ns	$ t_{PD\text{off}} - t_{PD\text{on}} $ ^{1) 3)}
Input pulse width that changes output state	$t_{pw,min}$	8	12.5	16	ns	Measured with full range of input signal $V_{IN} = V_{DDI}$ ⁴⁾
Output signal rise time	t_{rise}			4	ns	10% to 90% rising output, $C_{LOAD} = 15 \text{ pF}$
Output signal fall time	t_{fall}			4	ns	90% to 10% falling output, $C_{LOAD} = 15 \text{ pF}$
Output disable propagation delay (high output to high-impedance)	$t_{PD,HZ}$			10	ns	From 50% falling enable (except 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$ From 50% rising enable (for 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$
Output disable propagation delay (low output to high impedance)	$t_{PD,LZ}$			10	ns	From 50% of falling enable (except 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$ From 50% of rising enable (for 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$
Output enable propagation delay (high-impedance to high output)	$t_{PD,ZH}$			15	ns	From 50% rising enable (except 4DIR142xH) to 50% of rising V_{OH} From 50% falling enable (for 4DIR142xH) to 50% of rising V_{OH}

(table continues...)

4 Thermal and electrical characteristics

Table 21 (continued) **Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Output enable propagation delay (high-impedance to low output)	$t_{PD,ZL}$			14	ns	From 50% rising enable (except 4DIR142xH) to 50% of falling V_{OH} From 50% falling enable (for 4DIR142xH) to 50% of falling V_{OH}
Default output delay time from input power loss	t_{DO}		0.4	2.6	μs	Measured from $V_{DDIUVL0off} = 2.55 V$. Power supply ramp rate = 1 V/ μs
Time from UVLO to valid output data	t_{PU}			3	μs	Power supply ramp rate = 1 V/ μs , DR > 6.6 Mbps

- 1) Parameter tested in production
- 2) The parameter gives the difference in propagation delay between different samples switching in the same direction under same conditions, including same ambient temperature
- 3) Also known as pulse skew. The parameter gives the maximum difference between on and off propagation delay shown from the same sample over the operating temperature range
- 4) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2 Electrical characteristics - 5 V supply

Typical values are given at $T_A = 25\text{ °C}$, $V_{DD1} = V_{DD2} = 5\text{ V}$. Minimum/maximum specifications apply over the entire recommended operation range of $V_{DD1} = V_{DD2} = 5\text{ V} \pm 10\%$, and $-40\text{ °C} \leq T_A \leq +125\text{ °C}$, unless otherwise noted. Switching characteristics are tested with $C_{LOAD} = 15\text{ pF}$ and 50% duty cycle input square wave, over operating range unless otherwise specified. Supply current values are calculated considering all channels are switching at the same data rate. Parameters are tested in production unless otherwise specified. Only DC supply currents are tested in production and AC supply currents are not tested in production.

4.7.2.1 Logic inputs

Table 22 Logic inputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level input current	I_{IH}			10	μA	$V_{INX} = V_{DDI}$ ^{1) 2)}
Low-level input current	I_{IL}	-10			μA	$V_{INX} = 0\text{ V}$ ²⁾
Input voltage threshold for transition LH	V_{I_LH}			$0.7V_{DDI}$	V	
Input voltage threshold for transition HL	V_{I_HL}	$0.3V_{DDI}$			V	
Input voltage threshold hysteresis	V_{I_HYS}	$0.1V_{DDI}$			V	
Input pull-down resistor	R_{IN}		825		k Ω	$V_{INX} = V_{DDI}$ ¹⁾

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

2) Parameter not tested in production

4.7.2.2 Logic outputs

Table 23 Logic outputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level output voltage	V_{OH}	$V_{DDO} - 0.4$			V	$I_{OH} = 4\text{ mA}$ ¹⁾
Low-level output voltage	V_{OL}			0.4	V	$I_{OL} = -4\text{ mA}$

1) V_{DDO} - Output-side supply voltage. For output buffers on side 1 it is V_{DD1} and for output buffers on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2.3 Power supply - 4DIR040xH (4+0)

Table 24 Power supply - 4DIR040xH (4+0)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			3.1	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			1.85	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			3.1	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			1.85	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.9	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.1	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			9.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			4.2	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			17	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			6.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			32	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			11.5	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2.4 Power supply - 4DIR140xH (3+1)

Table 25 Power supply - 4DIR140xH (3+1)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.6	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.3	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			14.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			9.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			27	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			16	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2.5 Power supply - 4DIR240xH (2+2)

Table 26 Power supply - 4DIR240xH (2+2)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.65	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.65	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.65	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.65	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.3	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			3.3	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			7.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			7	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			13	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			12	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			23	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			21	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2.6 Power supply - 4DIR142xH (3+1 EN1 neg.)

Table 27 Power supply - 4DIR142xH (3+1 EN1 neg.)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.9	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.3	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.6	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.3	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			14.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			9.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			27	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			16	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.2.7 Dynamic characteristics

Table 28 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
INx to OUTx turn-on propagation delay	$t_{PD\text{on}}$	21	26	32	ns	From 50% level of rising input to 50% level of corresponding rising output
INx to OUTx turn-off propagation delay	$t_{PD\text{off}}$	21	26	32	ns	From 50% level of falling input to 50% level of corresponding falling output
Part-to-part propagation delays mismatch	$\Delta t_{PD,p-p}$			6	ns	¹⁾
Co-directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, same direction channels, switching in the same direction
Opposing directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, opposing directional channels, switching with the same signal level
Pulse width distortion	PWD			3	ns	$ t_{PD\text{off}} - t_{PD\text{on}} $ ²⁾
Input pulse width that changes output state	$t_{pw,min}$	8.5	12.5	15	ns	Measured with full range of input signal $V_{IN} = V_{DDI}$ ³⁾
Output signal rise time	t_{rise}			3.5	ns	10% to 90% rising output, $C_{LOAD} = 15 \text{ pF}$ ⁴⁾
Output signal fall time	t_{fall}			3.5	ns	90% to 10% falling output, $C_{LOAD} = 15 \text{ pF}$ ⁴⁾
Output disable propagation delay (high output to high-impedance)	$t_{PD,HZ}$			11	ns	From 50% falling enable (except 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$ From 50% rising enable (for 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$ ⁴⁾
Output disable propagation delay (low output to high-impedance)	$t_{PD,LZ}$			10	ns	From 50% of falling enable (except 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$ From 50% of rising enable (for 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$ ⁴⁾
Output enable propagation delay (high-impedance to high output)	$t_{PD,ZH}$			14	ns	From 50% rising enable (except 4DIR142xH) to 50% of rising V_{OH} From 50% falling enable (for 4DIR142xH) to 50% of rising V_{OH} ⁴⁾

(table continues...)

4 Thermal and electrical characteristics

Table 28 (continued) Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Output enable propagation delay (high-impedance to low output)	$t_{PD,ZL}$			13	ns	From 50% of rising enable (except 4DIR142xH) to 50% of falling V_{OH} From 50% of falling enable (for 4DIR142xH) to 50% of falling V_{OH} ⁴⁾
Default output delay time from input power loss	t_{DO}		0.4	2.6	μs	Measured from $V_{DDIUVLOoff} = 2.55 V$. Power supply ramp rate = 1 V/ μs
Time from UVLO to valid output data	t_{PU}			3	μs	Power supply ramp rate = 1 V/ μs , DR > 6.6 Mbps ⁴⁾

- 1) The parameter gives the difference in propagation delay between different samples switching in the same direction under same conditions, including same ambient temperature
- 2) Also known as pulse skew. The parameter gives the maximum difference between on and off propagation delay shown from the same sample over the operating temperature range
- 3) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}
- 4) Parameter not tested in production

4 Thermal and electrical characteristics

4.7.3 Electrical characteristics - 3.3 V supply

Typical values are given at $T_A = 25^\circ\text{C}$, $V_{DD1} = V_{DD2} = 3.3\text{V}$. Minimum/maximum specifications apply over the entire recommended operation range of $V_{DD1} = V_{DD2} = 3.3\text{V} \pm 10\%$, and $-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$, unless otherwise noted. Switching characteristics are tested with $C_{LOAD} = 15\text{ pF}$ and 50% duty cycle input square wave, over operating range unless otherwise specified. Supply current values are calculated considering all channels are switching at the same data rate. Parameters are tested in production unless otherwise specified. Only DC supply currents are tested in production and the AC supply currents are not tested in production.

4.7.3.1 Logic inputs

Table 29 Logic inputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level input current	I_{IH}			10	μA	$V_{INX} = V_{DDI}$ ^{1) 2)}
Low-level input current	I_{IL}	-10			μA	$V_{INX} = 0\text{ V}$ ²⁾
Input voltage threshold for transition LH	V_{I_LH}			$0.7V_{DDI}$	V	
Input voltage threshold for transition HL	V_{I_HL}	$0.3V_{DDI}$			V	
Input voltage threshold hysteresis	V_{I_HYS}	$0.1 V_{DDI}$			V	
Input pull-down resistor	R_{IN}		825		k Ω	$V_{INX} = V_{DDI}$ ^{1) 2)}

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

2) Parameter not tested in production

4.7.3.2 Logic outputs

Table 30 Logic outputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level output voltage	V_{OH}	$V_{DDO} - 0.3$			V	$I_{OH} = 2\text{ mA}$ ¹⁾
Low-level output voltage	V_{OL}			0.3	V	$I_{OL} = -2\text{ mA}$

1) V_{DDO} - Output-side supply voltage. For output buffers on side 1 it is V_{DD1} and for output buffers on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.3.3 Power supply - 4DIR040xH (4+0)

Table 31 Power supply - 4DIR040xH (4+0)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			3.05	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			1.8	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			3.05	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			1.8	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.8	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			9.2	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			3.6	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			16	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			5.5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			32	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			9	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.3.4 Power supply - 4DIR140xH (3+1)

Table 32 Power supply - 4DIR140xH (3+1)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.85	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.25	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.85	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.25	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.1	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			14	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			8	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			26	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			14	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.3.5 Power supply - 4DIR240xH (2+2)

Table 33 Power supply - 4DIR240xH (2+2)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.6	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.6	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.6	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.6	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			3.2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			7	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			6.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			12	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			11	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			21	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			19	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.3.6 Power supply - 4DIR142xH (3+1 EN1 neg.)

Table 34 Power supply - 4DIR142xH (3+1 EN1 neg.)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.85	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.25	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.85	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.25	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8.1	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			14	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			8	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			26	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			14	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.3.7 Dynamic characteristics

Table 35 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
INx to OUTx turn-on propagation delay	t_{PDOn}	21	26	32	ns	From 50% level of rising input to 50% level of rising output
INx to OUTx turn-off propagation delay	t_{PDOff}	21	26	32	ns	From 50% level of falling input to 50% level of falling output
Part-to-part propagation delays mismatch	$\Delta t_{PD,p-p}$			6	ns	¹⁾
Co-directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, same direction channels, switching in the same direction
Opposing directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, opposing directional channels, switching with the same signal level.
Pulse width distortion	PWD			3	ns	$ t_{PDOff} - t_{PDOn} $ ²⁾
Input pulse width that changes output state	$t_{pw,min}$	9	12.5	15	ns	Measured with full range of input signal $V_{IN} = V_{DDI}$ ³⁾
Output signal rise time	t_{rise}			3.5	ns	10% to 90% rising output, $C_{LOAD} = 15 \text{ pF}$ ⁴⁾
Output signal fall time	t_{fall}			3.5	ns	90% to 10% falling output, $C_{LOAD} = 15 \text{ pF}$ ⁴⁾
Output disable propagation delay (high output to high-impedance)	$t_{PD,HZ}$			13	ns	From 50% falling enable (except 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$ From 50% rising enable (for 4DIR142xH) to $V_{OH} - 0.5 \text{ V}$ ⁴⁾
Output disable propagation delay (low output to high-impedance)	$t_{PD,LZ}$			12	ns	From 50% of falling enable (except 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$ From 50% of rising enable (for 4DIR142xH) to $V_{OL} + 0.5 \text{ V}$ ⁴⁾
Output enable propagation delay (high-impedance to high output)	$t_{PD,ZH}$			14	ns	From 50% rising enable (except 4DIR142xH) to 50% of rising V_{OH} From 50% falling enable (for 4DIR142xH) to 50% of rising V_{OH} ⁴⁾

(table continues...)

4 Thermal and electrical characteristics

Table 35 (continued) Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Output enable propagation delay (high-impedance to low output)	$t_{PD,ZL}$			13	ns	From 50% of rising enable (except 4DIR142xH) to 50% of falling V_{OH} From 50% of falling enable (for 4DIR142xH) to 50% of falling V_{OH} ⁴⁾
Default output delay time from input power loss	t_{DO}		0.4	2.6	μs	Measured from $V_{DDIUVLOoff} = 2.55 V$. Power supply ramp rate = 1 V/ μs
Time from UVLO to valid output data	t_{PU}			3	μs	Power supply ramp rate = 1 V/ μs , DR > 6.6 Mbps ⁴⁾

- 1) The parameter gives the difference in propagation delay between different samples switching in the same direction under same conditions, including same ambient temperature
- 2) Also known as pulse skew. The parameter gives the maximum difference between on and off propagation delay shown from the same sample over the operating temperature range
- 3) V_{DDI} - Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}
- 4) Parameter not tested in production

4 Thermal and electrical characteristics

4.7.4 Electrical characteristics - 2.7 V supply

Typical values are given at $T_A = 25^\circ\text{C}$ with $V_{DD1} = V_{DD2} = 2.7\text{ V}$. Minimum/maximum specifications apply over the entire recommended operation range of $V_{DD1} = V_{DD2} = 2.7\text{ V}$, and $-40^\circ\text{C} \leq T_A \leq 125^\circ\text{C}$, unless otherwise noted. Switching characteristics are tested with $C_{\text{LOAD}} = 15\text{ pF}$ and 50% duty-cycle input square wave, over operating range unless otherwise specified. Supply current values are specified considering that all channels are switching at the same data rate. Parameters are not tested in production unless otherwise specified.

4.7.4.1 Logic inputs

Table 36 Logic inputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level input current	I_{IH}			10	μA	$V_{\text{INX}} = V_{\text{DDI}}$ ¹⁾
Low-level input current	I_{IL}	-10			μA	$V_{\text{INX}} = 0\text{ V}$
Input voltage threshold for transition LH	V_{I_LH}			$0.7 V_{\text{DDI}}$	V	
Input voltage threshold for transition HL	V_{I_HL}	$0.3 V_{\text{DDI}}$			V	
Input voltage threshold hysteresis	V_{I_HYS}	$0.1 V_{\text{DDI}}$			V	
Input pull-down resistor	R_{IN}		825		$\text{k}\Omega$	$V_{\text{INX}} = V_{\text{DDI}}$ ¹⁾

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4.7.4.2 Logic outputs

Table 37 Logic outputs

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
High-level output voltage	V_{OH}	$V_{\text{DDO}} - 0.3$			V	$I_{OH} = 1\text{ mA}$ ¹⁾
Low-level output voltage	V_{OL}			0.3	V	$I_{OL} = -1\text{ mA}$

1) V_{DDO} - Output-side supply voltage. For output buffers on side 1 it is V_{DD1} and for output buffers on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.4.3 Power supply - 4DIR040xH (4+0)

Table 38 Power supply - 4DIR040xH (4+0)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			3	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			1.75	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			3	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			1.75	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.75	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			1.95	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			9.2	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			3.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			16	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			5	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			32	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			8	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.4.4 Power supply - 4DIR140xH (3+1)

Table 39 Power supply - 4DIR140xH (3+1)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.8	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.2	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.8	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.2	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			13.8	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			7.6	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			26	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			13	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.4.5 Power supply - 4DIR240xH (2+2)

Table 40 Power supply - 4DIR240xH (2+2)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.6	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.6	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.6	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.6	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			3.2	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			7	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			6.5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			12	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			11	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			21	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			19	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.4.6 Power supply - 4DIR142xH (3+1 EN1 neg.)

Table 41 Power supply - 4DIR142xH (3+1 EN1 neg.)

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply current - DC input	I_{DD1}			2.8	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD2}			2.2	mA	$V_{INx} = V_{DDI}$ ¹⁾
Supply current - DC input	I_{DD1}			2.8	mA	$V_{INx} = 0\text{ V}$
Supply current - DC input	I_{DD2}			2.2	mA	$V_{INx} = 0\text{ V}$
Supply current - AC input	I_{DD1_1Mb}			3.5	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD2_1Mb}			2.4	mA	$DR = 1\text{ Mbps}$
Supply current - AC input	I_{DD1_10Mb}			8	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD2_10Mb}			5	mA	$DR = 10\text{ Mbps}$
Supply current - AC input	I_{DD1_20Mb}			13.8	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD2_20Mb}			7.6	mA	$DR = 20\text{ Mbps}$
Supply current - AC input	I_{DD1_40Mb}			26	mA	$DR = 40\text{ Mbps}$
Supply current - AC input	I_{DD2_40Mb}			13	mA	$DR = 40\text{ Mbps}$

1) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.7.4.7 Dynamic characteristics

Table 42 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
INx to OUTx turn-on propagation delay	t_{PDOn}	20	26	33	ns	From 50% level of rising input to 50% level of corresponding rising output ¹⁾
INx to OUTx turn-off propagation delay	t_{PDOff}	20	26	33	ns	From 50% level of falling input to 50% level of corresponding falling output ¹⁾
Part-to-part propagation delays mismatch	$\Delta t_{PD,p-p}$			6	ns	^{1) 2)}
Co-directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, same direction channels, switching in the same direction ¹⁾
Opposing directional channel-to-channel propagation delay mismatch	$\Delta t_{PD,Ch-Ch}$			3	ns	Within same sample, over operating temperature range, opposing directional channels, switching with the same signal level ¹⁾
Pulse width distortion	PWD			3.5	ns	$ t_{PDOff} - t_{PDOn} $ ^{1) 3)}
Input pulse width that changes output state	$t_{pw,min}$	8.5	12.5	16	ns	Measured with full range of input signal $V_{IN} = V_{DDI}$ ^{1) 4)}
Output signal rise time	t_{rise}			3	ns	10% to 90% rising output, $C_{LOAD} = 15$ pF
Output signal fall time	t_{fall}			3	ns	90% to 10% falling output, $C_{LOAD} = 15$ pF
Output disable propagation delay (high output to high-impedance)	$t_{PD,HZ}$			13	ns	From 50% falling enable (except 4DIR142xH) to $V_{OH} - 0.5$ V From 50% rising enable (for 4DIR142xH) to $V_{OH} - 0.5$ V
Output disable propagation delay (low output to high-impedance)	$t_{PD,LZ}$			13	ns	From 50% of falling enable (except 4DIR142xH) to $V_{OL} + 0.5$ V From 50% of rising enable (for 4DIR142xH) to $V_{OL} + 0.5$ V
Output enable propagation delay (high-impedance to high output)	$t_{PD,ZH}$			14	ns	From 50% rising enable (except 4DIR142xH) to 50% of rising V_{OH} From 50% falling enable (for 4DIR142xH) to 50% of rising V_{OH}

(table continues...)

4 Thermal and electrical characteristics

Table 42 (continued) **Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Output enable propagation delay (high-impedance to low output)	$t_{PD,ZL}$			13	ns	From 50% of rising enable (except 4DIR142xH) to 50% of falling V_{OH} From 50% of falling enable (for 4DIR142xH) to 50% of falling V_{OH}
Default output delay time from input power loss	t_{DO}		0.4	2.6	μs	Measured from $V_{DDIUVLOoff} = 2.55 V$. Power supply ramp rate = 1 V/ μs ¹⁾
Time from UVLO to valid output data	t_{PU}			3	μs	Power supply ramp rate = 1 V/ μs , DR > 6.6 Mbps

1) Parameter tested in production

2) The parameter gives the difference in propagation delay between different samples switching in the same direction under same conditions, including same ambient temperature

3) Also known as pulse skew. The parameter gives the maximum difference between on and off propagation delay shown from the same sample over the operating temperature range

4) V_{DDI} = Input-side supply voltage. For input channels on side 1 it is V_{DD1} and for input channels on side 2 it is V_{DD2}

4 Thermal and electrical characteristics

4.8 Insulation and safety-related specifications

This coupler is suitable for rated insulation only within the safety limiting values. Compliance with the safety limiting values shall be ensured by means of suitable protective circuits.

4.8.1 Insulation characteristics

Parameter	Symbol	Value	Unit	Note or condition
External clearance	<i>CLR</i>	>8	mm	Shortest distance in air from any input pin to any output pin according to IEC 60664-1 ¹⁾
External creepage	<i>CRP</i>	>8	mm	Shortest distance over package surface from any input pin to any output pin according to IEC 60664-1 ¹⁾
Comparative tracking index	<i>CTI</i>	≥600	V	According to IEC 60112
Material group		I		According to IEC 60112
Pollution degree		2		According to IEC 60664-1
Overvoltage category		I - IV		Rated mains voltage ≤ 150 V _{RMS} According to IEC 60664-1
Overvoltage category		I - IV		Rated mains voltage ≤ 300 V _{RMS} According to IEC 60664-1
Overvoltage category		I - III		Rated mains voltage ≤ 600 V _{RMS} According to IEC 60664-1
Overvoltage category		I-II		Rated mains voltage ≤ 1000 V _{RMS} According to IEC 60664-1
Climatic category		40/125 /21		

Input-to-output isolation according to UL1577 Ed. 5

Input-to-output isolation voltage	V_{ISO}	5700	V _{rms}	$V_{TEST} = V_{ISO}$ for $t = 60$ s (qualification); $V_{TEST} = 1.2 \times V_{ISO}$ for $t = 1$ s (100% productive tests)
-----------------------------------	-----------	------	------------------	---

Input-to-output isolation according to DIN VDE V 0884-17, IEC 60747-17²⁾

Maximum rated transient isolation voltage	V_{IOTM}	8000	V _{pk}	$V_{TEST} = V_{IOTM}$ for $t_{ini} = 60$ s (type test and sample test) $V_{TEST} = 1.2 \times V_{IOTM}$ for $t_{ini} = 1$ s (routine test)
Maximum Impulse voltage	V_{IMP}	8000	V _{pk}	According to IEC 60664-1, IEC 60747-17
Maximum rated repetitive peak isolation voltage	V_{IORM}	1131	V _{pk}	According to Time Dependent Dielectric Breakdown (TDDB) test

4 Thermal and electrical characteristics

Parameter	Symbol	Value	Unit	Note or condition
Apparent charge	q_{PD}	<5	pC	Method (b1) (routine test and type test pre-conditioning) $V_{PD(ini)} = 1.2 \times V_{IOTM}$ for $t_{ini} = 1$ s $V_{PD(m)} = 1.875 \times V_{IORM}$ for $t_m = 1$ s ³⁾ Method (a) (type test, subgroup 1 final measurements) $V_{PD(ini)} = V_{IOTM}$ for $t_{ini} = 60$ s $V_{PD(m)} = 1.6 \times V_{IORM}$ for $t_m = 10$ s Method (a) (type test, subgroup 2, 3 final measurements) $V_{PD(ini)} = V_{IOTM}$ for $t_{ini} = 60$ s $V_{PD(m)} = 1.2 \times V_{IORM}$ for $t_m = 10$ s
Maximum surge isolation voltage	V_{IOSM}	11000	V _{pk}	$V_{IOSM} = 11$ kV _{pk} $\geq 1.3 \times V_{IMP}$ for reinforced isolation according to IEC 60747-17 (type test) ⁴⁾
Isolation resistance ⁶⁾	R_{IO}	$>10^{12}$	Ω	$V_{IO} = 500$ V _{dc} for $t = 60$ s, $T_A = 25^\circ\text{C}$ ⁵⁾
		$>10^{11}$	Ω	$V_{IO} = 500$ V _{dc} for $t = 60$ s, $T_A = 125^\circ\text{C}$ ⁵⁾
	R_{IO_S}	$>10^9$	Ω	$V_{IO} = 500$ V _{dc} for $t = 60$ s, $T_A = T_S = 150^\circ\text{C}$ ⁵⁾
Isolation capacitance ⁶⁾	C_{IO}	<2	pF	$f = 1$ MHz ⁵⁾

1) Creepage and clearance requirements depend on the application and related end-equipment isolation standard. Care should be taken to keep the required creepage and clearance value on printed circuit board level.

2) Safety certification planned. The IEC 60747-17 and its German equivalent VDE 0884-17 is the successor of the component standard VDE 0884-11, which will expire in 2023.

3) The partial discharge voltage $V_{PD(m)}$ applied during productive tests is greater (4411 V_{pk} $> 1.875 \times V_{IORM}$) to include the F_4 factor (1.1) that takes into account the maximum deviation of the mains supply voltage from its nominal value as specified by end-equipment standards IEC 60664-1, IEC 62368-1 ($V_{PD(m)} = F_1 \times F_2 \times F_3 \times F_4 \times V_{IORM} = 1.875 \times F_4 \times V_{IORM}$). The F_3 factor (1.25) is also considered for reinforced isolation as specified in IEC 60664-1.

4) The surge test is performed in insulation oil to determine the intrinsic surge immunity of the insulation barrier.

5) The parameters apply to the product converted in a two terminals device with all terminals on side 1 connected together and all terminals on side 2 connected together.

6) Parameter not tested in production.

4 Thermal and electrical characteristics

4.8.2 Safety-limiting values

This coupler is suitable for rated insulation only within the safety limiting values. Compliance with the safety limiting values shall be ensured by means of suitable protective circuits.

Parameter	Symbol	Value	Unit	Note or condition
Maximum ambient safety temperature	T_S	150	°C	
Safety power dissipation	P_S	2.08	W	$R_{thJA} = 60 \text{ K/W}$, $T_A = 25 \text{ °C}$, $T_J = 150 \text{ °C}$
Safety supply current	$I_{S,TOT}$	416	mA	$R_{thJA} = 60 \text{ K/W}$, $T_A = 25 \text{ °C}$, $T_J = 150 \text{ °C}$, $V_{DDX} = 5.0 \text{ V}$

4.8.2.1 Thermal derating curve

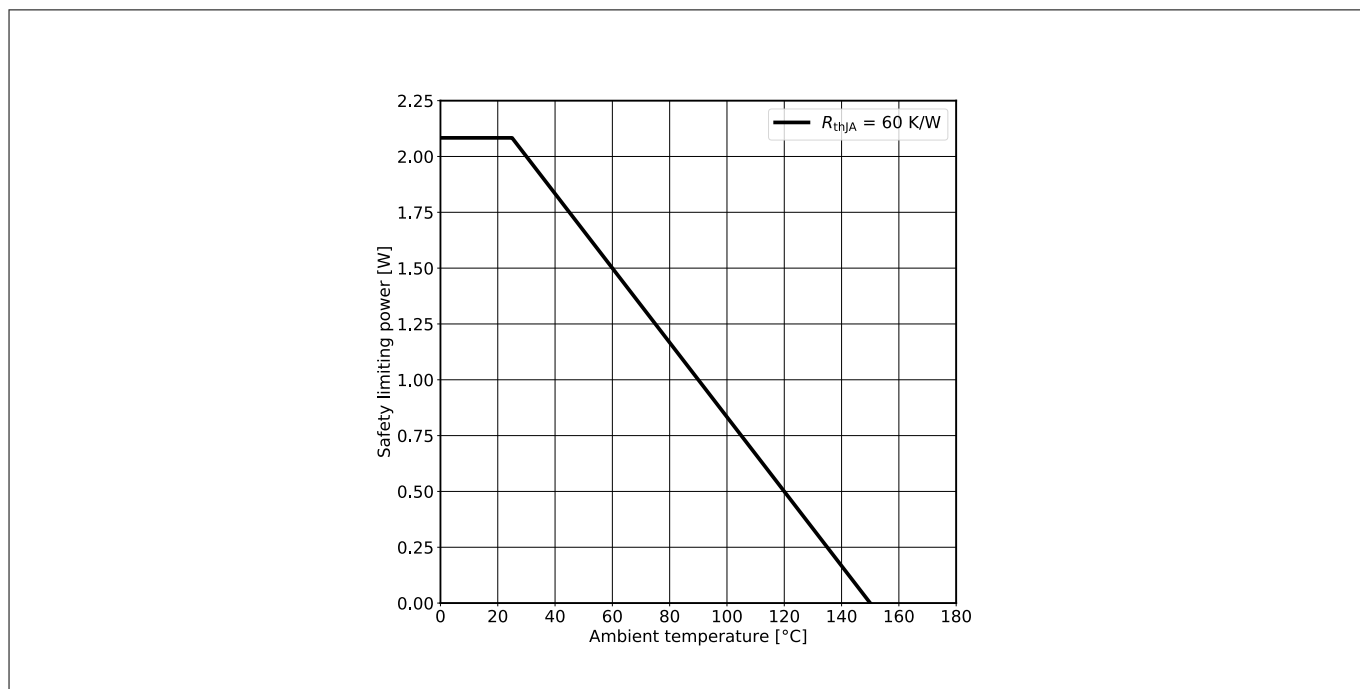


Figure 37 Thermal derating curve

5 Package dimensions

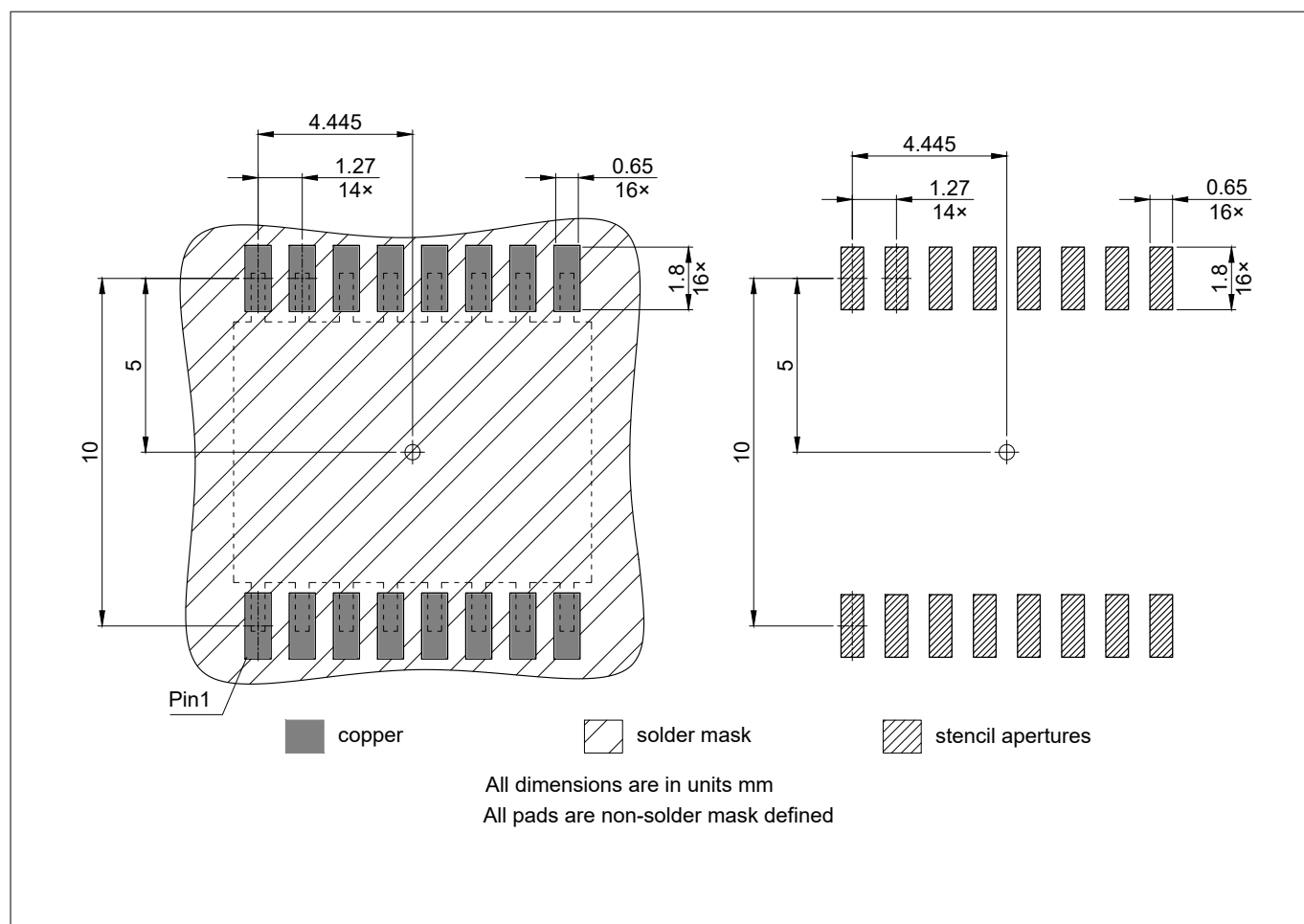


Figure 39 PG-DSO-16 wide-body 300 mil footprint

5 Package dimensions

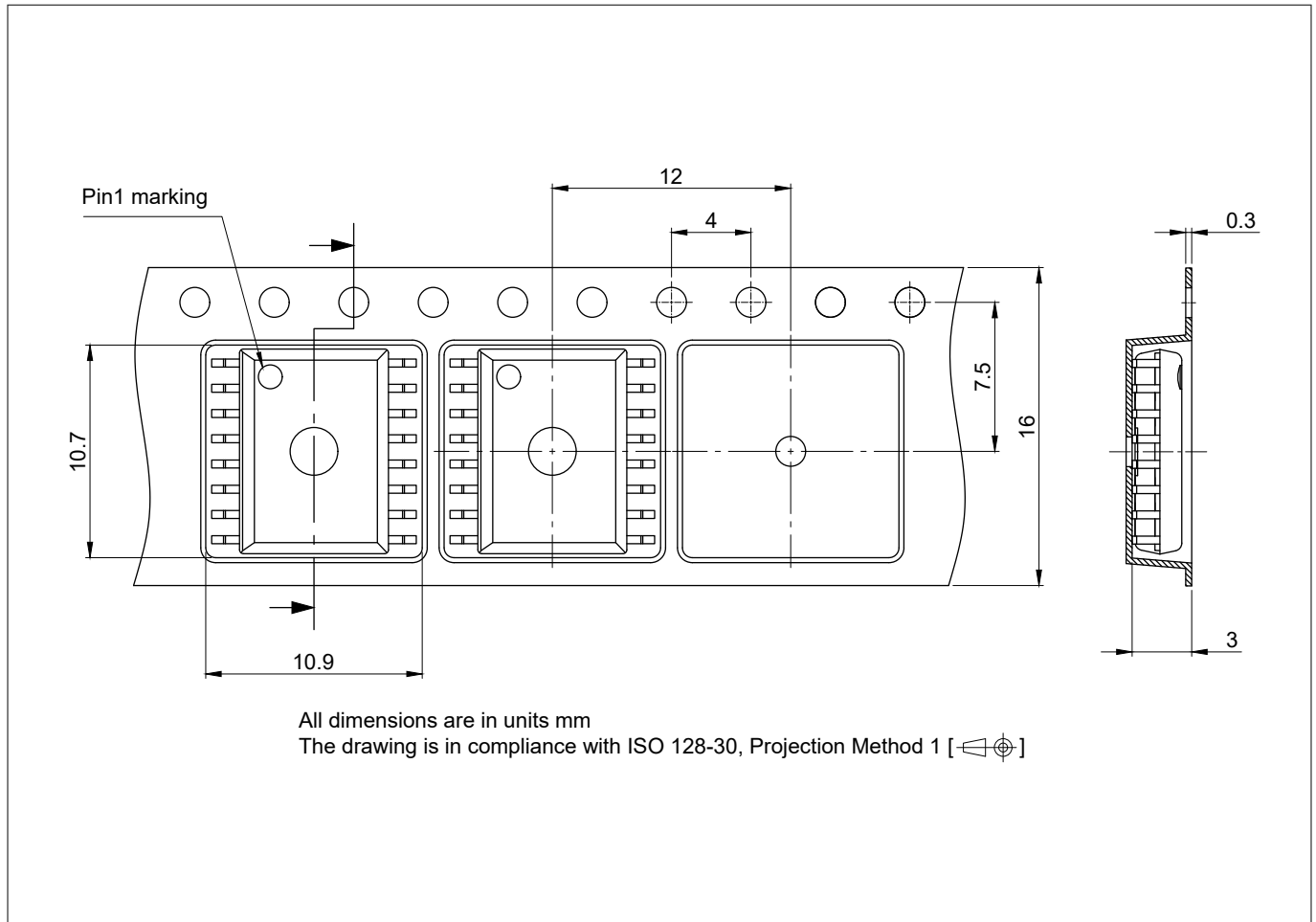


Figure 40 PG-DSO-16 wide-body 300 mil packing

Green product (RoHS-compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations, the device is available as a green product. Green products are RoHS-compliant (i.e. they have Pb-free finish on leads and are suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Further information on packages: <https://www.infineon.com/packages>

6 Ordering guide

6 Ordering guide

Orderable part number (OPN)	Part number	Channel configuration	Default output state	Output enable	Package marking
4DIR0400HXUMA1	4DIR0400H	4 forward 0 reverse (4+0)	Low	Active-high	4R0400A
4DIR0401HXUMA1	4DIR0401H		High		4R0401A
4DIR1400HXUMA1	4DIR1400H	3 forward 1 reverse (3+1)	Low		4R1400A
4DIR1401HXUMA1	4DIR1401H		High		4R1401A
4DIR2400HXUMA1	4DIR2400H	2 forward 2 reverse (2+2)	Low		4R2400A
4DIR2401HXUMA1	4DIR2401H		High		4R2401A
4DIR1420HXUMA1	4DIR1420H	3 forward 1 reverse (3+1)	Low	Active-low ¹⁾	4R1420A
4DIR1421HXUMA1	4DIR1421H		High		4R1421A

1) Ideal for shared SPI bus

7 Revision history

7 Revision history

Revision number	Major changes since previous revision
V1.4, 2024-02-08	Changed V_{IOSM} from 6875 V_{pk} to 10000 V_{pk} in Cover page
V1.3, 2023-12-05	Added 4 forward and 0 reverse (4+0) variant (4DIR040xHA) to the portfolio
V1.2, 2023-11-13	Figure 1 updated
V1.1, 2023-10-05	Changed V_{IORM} from 1767 V_{PK} to 1131 V_{PK}
V1.0, 2023-07-26	Datasheet initial release

Trademarks

All referenced product or service names and trademarks are the property of their respective owners.

Edition 2024-02-08

Published by

Infineon Technologies AG
81726 Munich, Germany

© 2024 Infineon Technologies AG
All Rights Reserved.

Do you have a question about any aspect of this document?

Email: erratum@infineon.com

Document reference
IFX-sgd1677063257744

Important notice

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics ("Beschaffenhheitsgarantie").

With respect to any examples, hints or any typical values stated herein and/or any information regarding the application of the product, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights of any third party.

In addition, any information given in this document is subject to customer's compliance with its obligations stated in this document and any applicable legal requirements, norms and standards concerning customer's products and any use of the product of Infineon Technologies in customer's applications.

The data contained in this document is exclusively intended for technically trained staff. It is the responsibility of customer's technical departments to evaluate the suitability of the product for the intended application and the completeness of the product information given in this document with respect to such application.

Warnings

Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

Except as otherwise explicitly approved by Infineon Technologies in a written document signed by authorized representatives of Infineon Technologies, Infineon Technologies' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.